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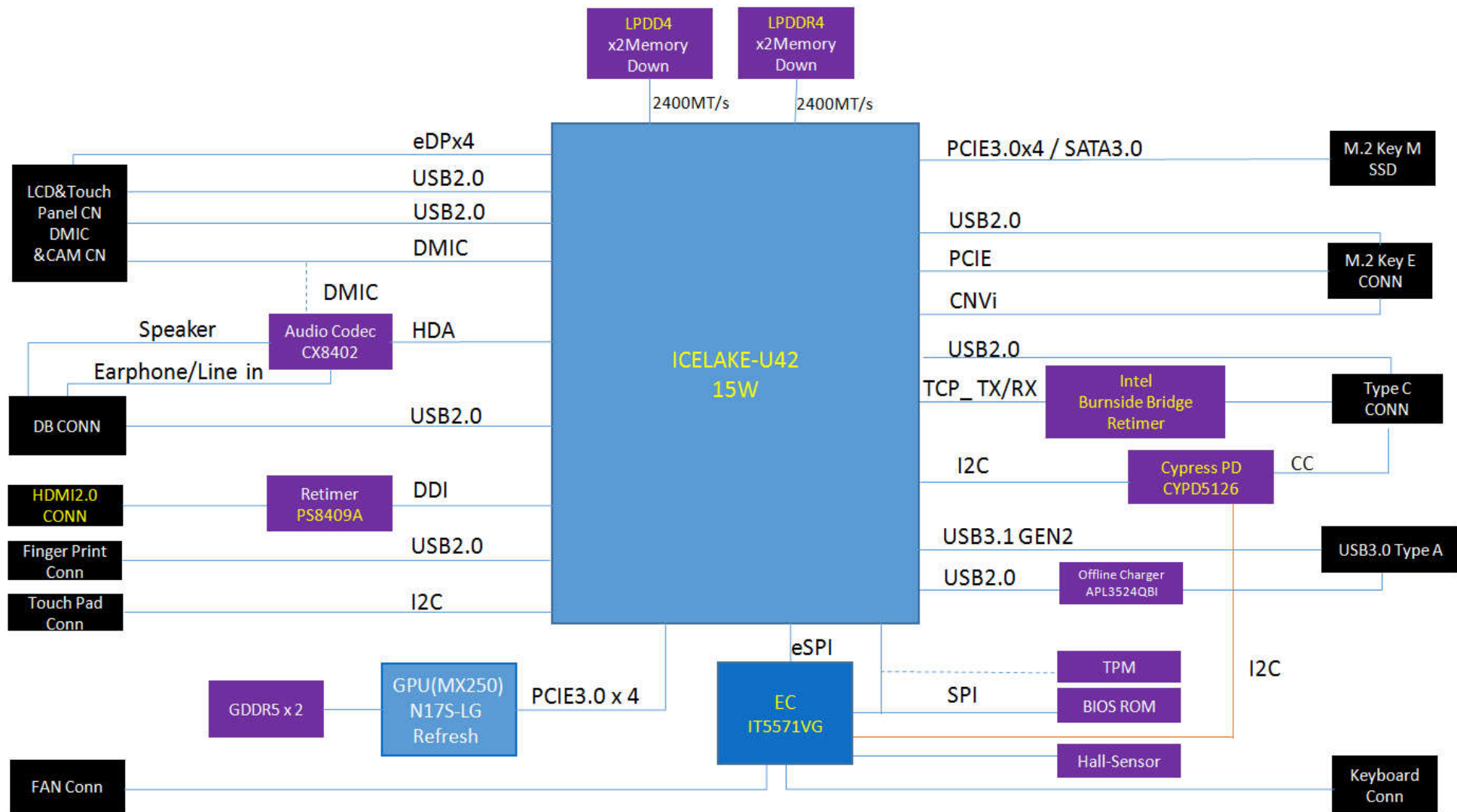
NB8511/12_M/B Schematics Document

Intel ICL Lake U-Processor with LPDDR4

REV1.0

2019-02-01

Author	Leo.Liu & Payne.Zhang	 Huaqin Telecom Technology Com.,Ltd.		
Reviewer	Nelosl.Hai & Nemo.Jiang	Page name: Cover page		
Approver	Lobo_Fan	Size: A4	Project Name: NB8511	REV: V1.0
		Date: Monday, July 15, 2019	Sheet: 1	of 72



MEM ID

HW_ID3	HW_ID2	HW_ID1	HW_ID0	Description	Total
0	0	0	0	SAMSUNG LPDDR4 3733 1GB K4F8E304HB-MGCJ LF+HF D20	4GB
0	0	0	1	HYNIX LPDDR4 3733 1GB H9HCNNN8KUMLHR-NME LF+HF DDP	4GB
0	0	1	0	MICRON LPDDR4 4266 2GB MT53E512M32D2NP-046 WT:E LF+HF Z11N	8GB
0	1	0	0	HYNIX LPDDR4 3733 2GB H9HCNNNBPUMLHR-NME LF+HF DE	8GB
0	1	0	0		16GB
1	0	0	0	HYNIX LPDDR4X 4266 4GB H9HCNNNCFMALHR-NEE LF+HF QDP	
				4x 16Gb(reserve)	

GPU ID

HW_ID5	HW_ID4	Description	
		N17-LG-Refresh	N17-LG
0	0	NC	NC
1	0	Mount	
1	1		Mount

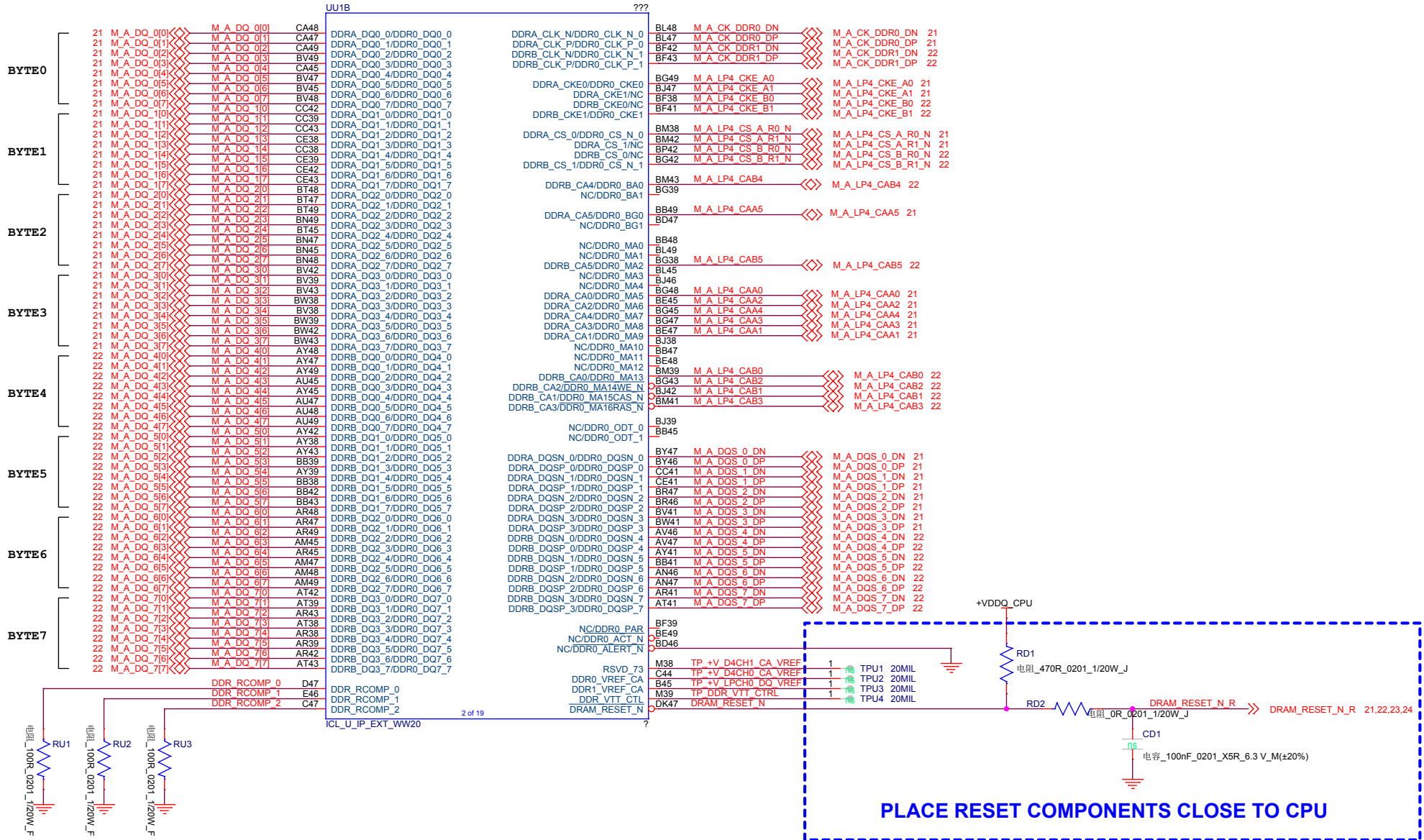
KB BL ID

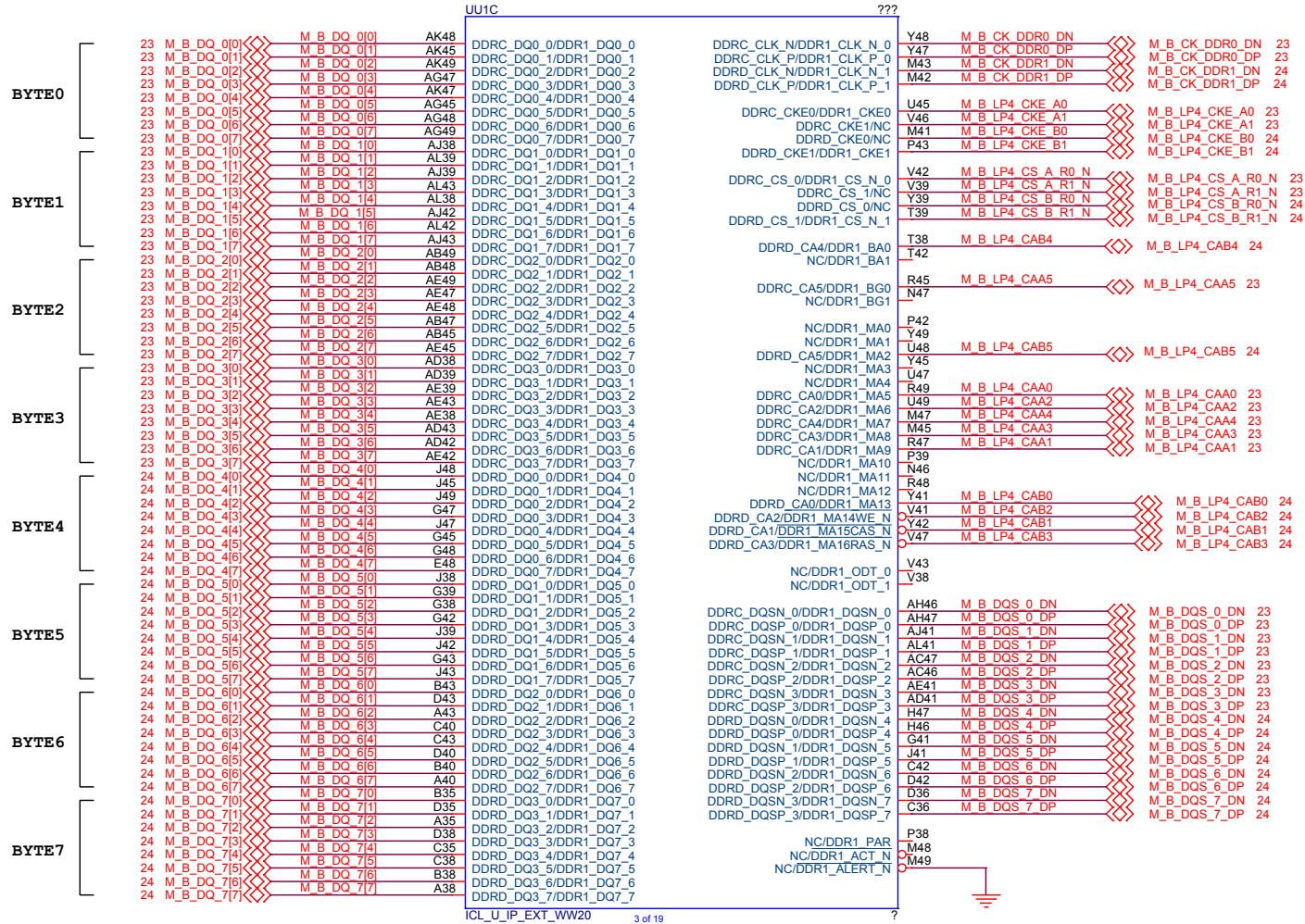
HW_ID6	Description
0	No keyboard Backlight
1	Keyboard Backlight

Reserve ID

HW_ID7	Description
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1	Reserve

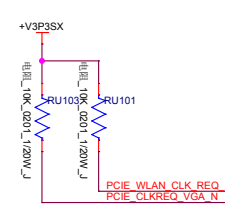
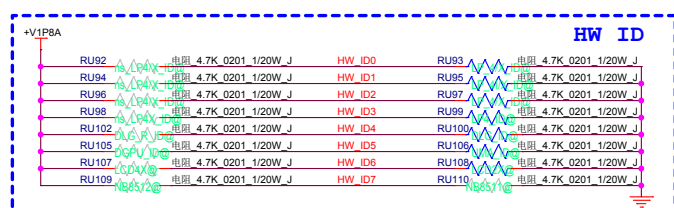
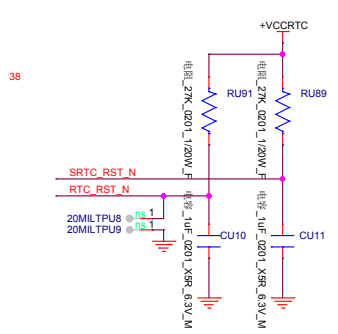
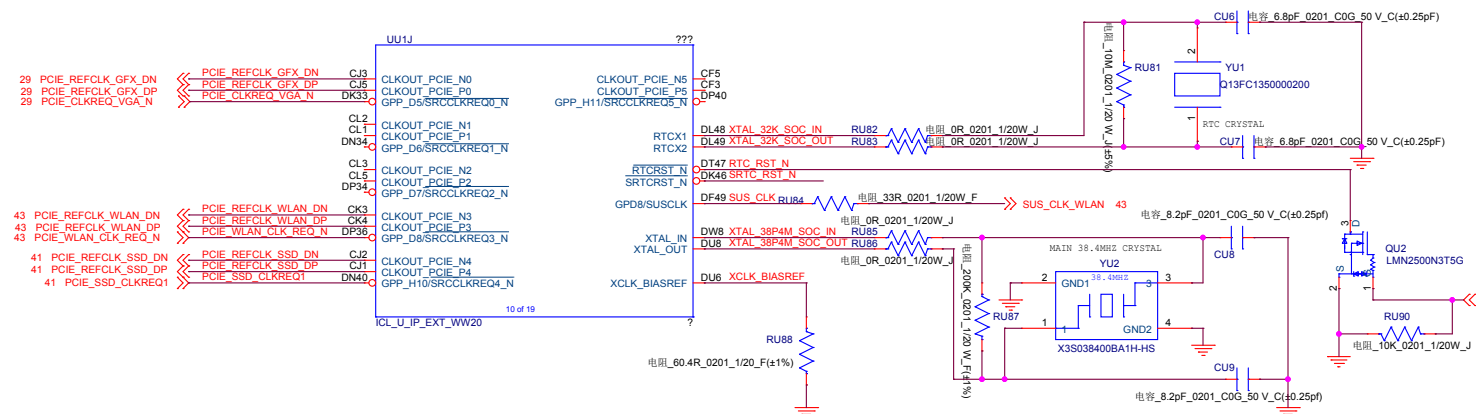
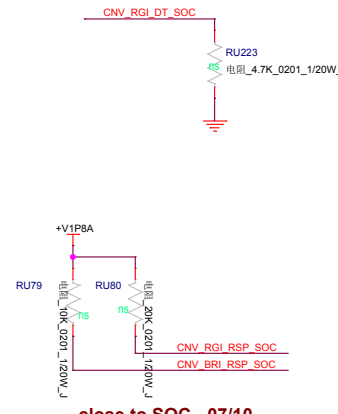
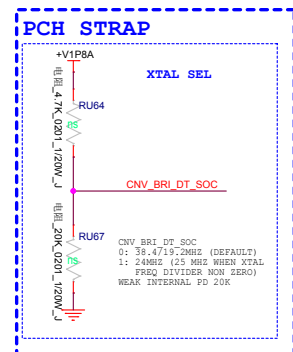
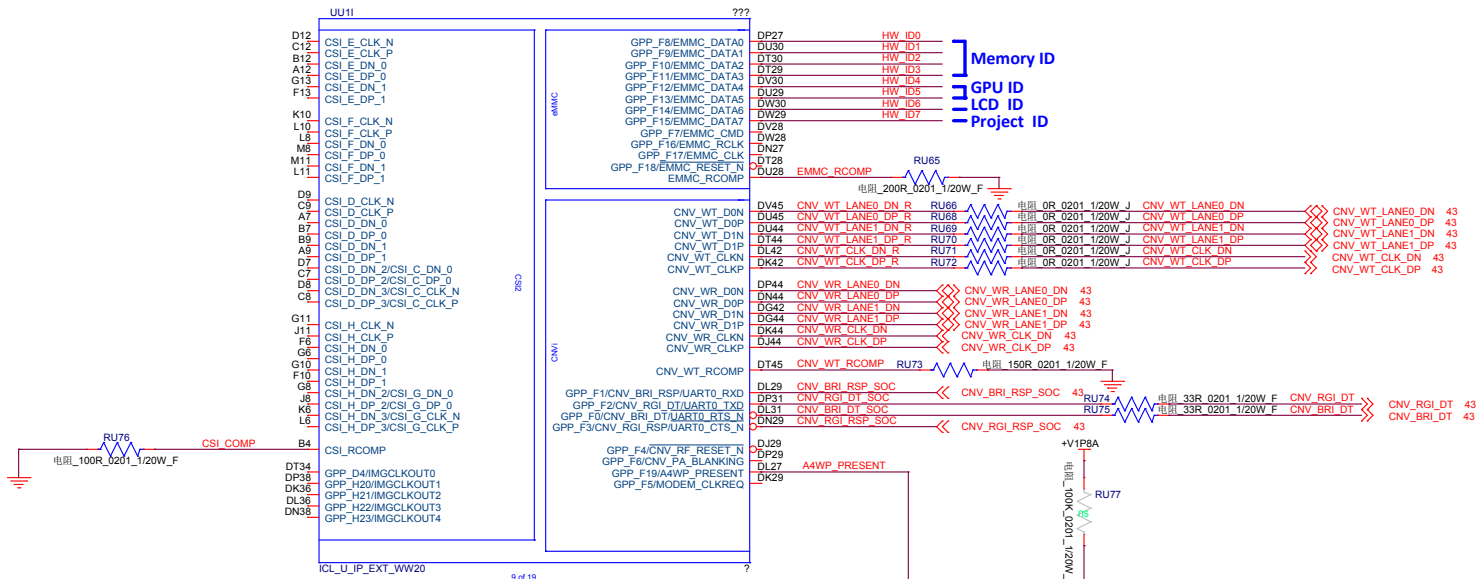
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C				C
B				B
A				A
5	4	3	2	1

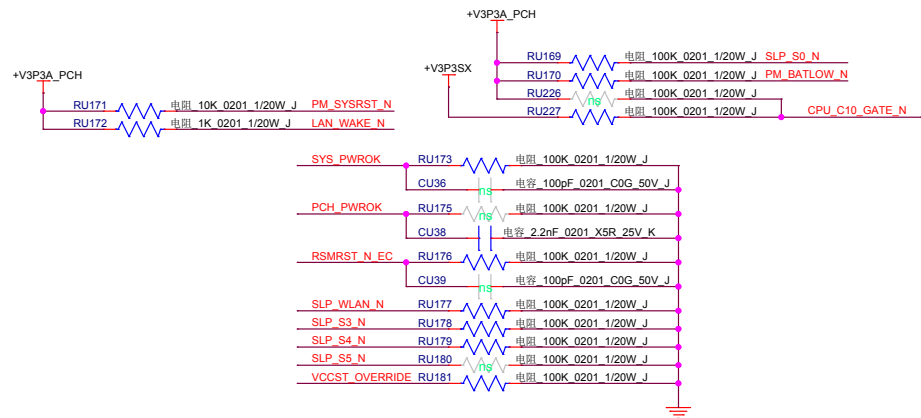
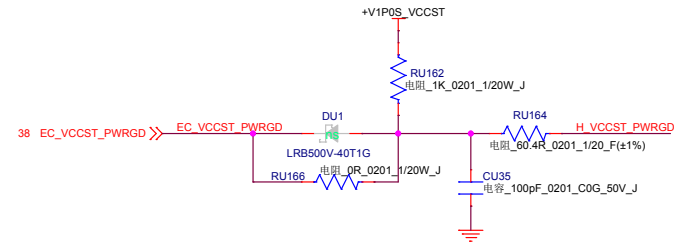
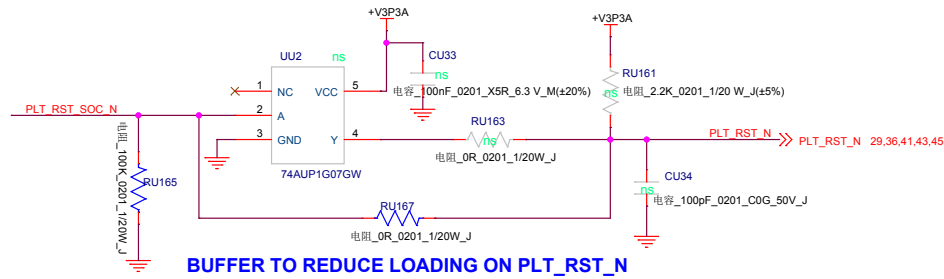
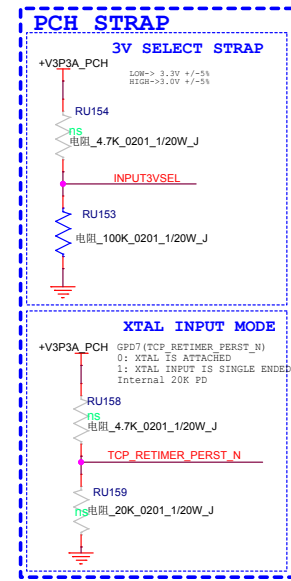
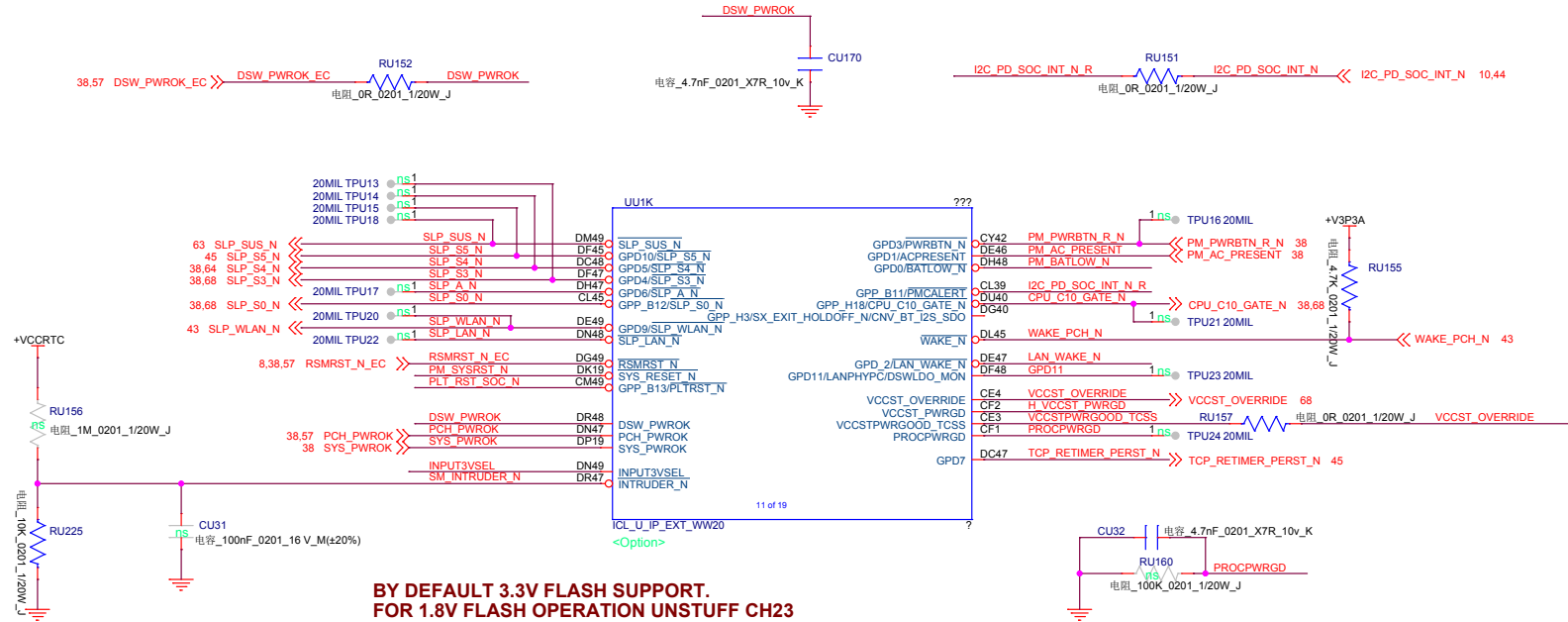




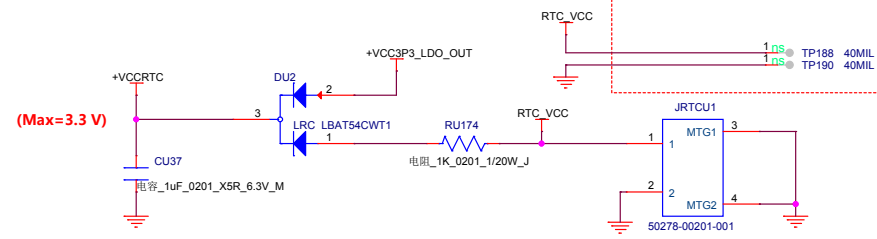
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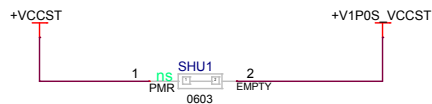
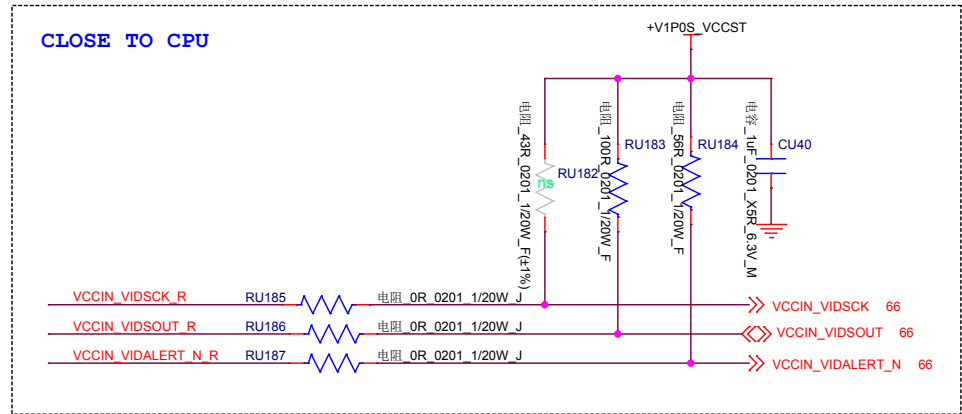
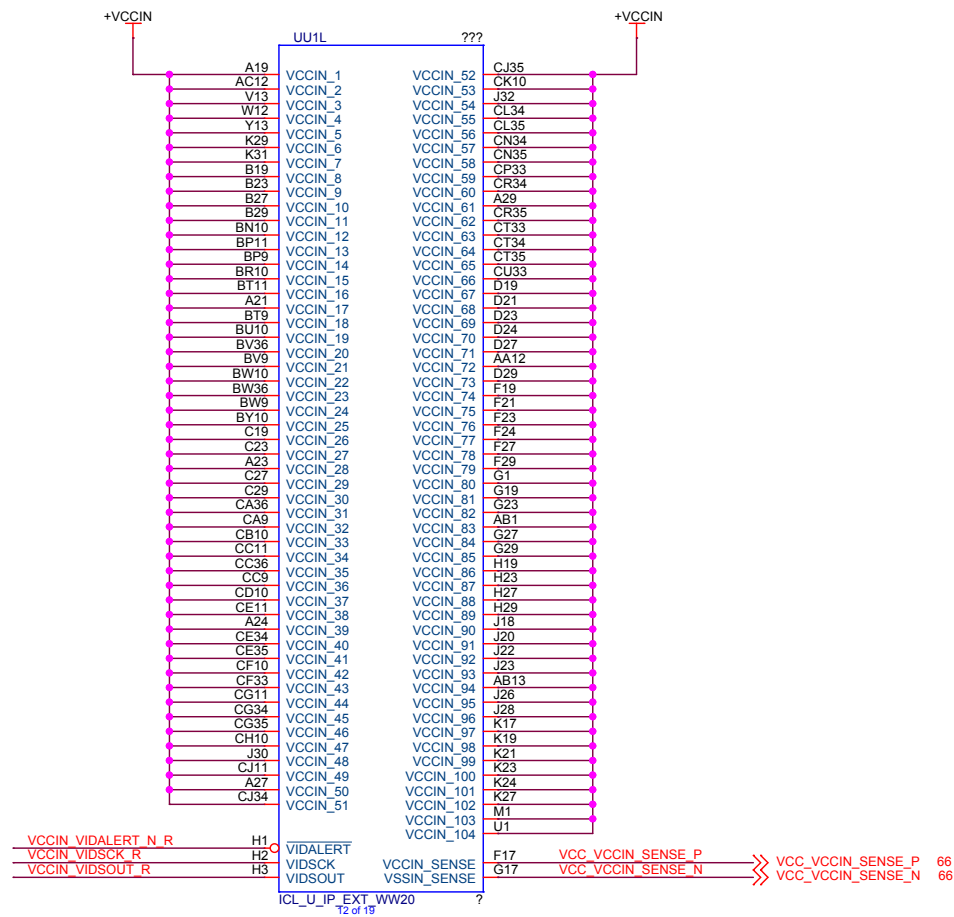


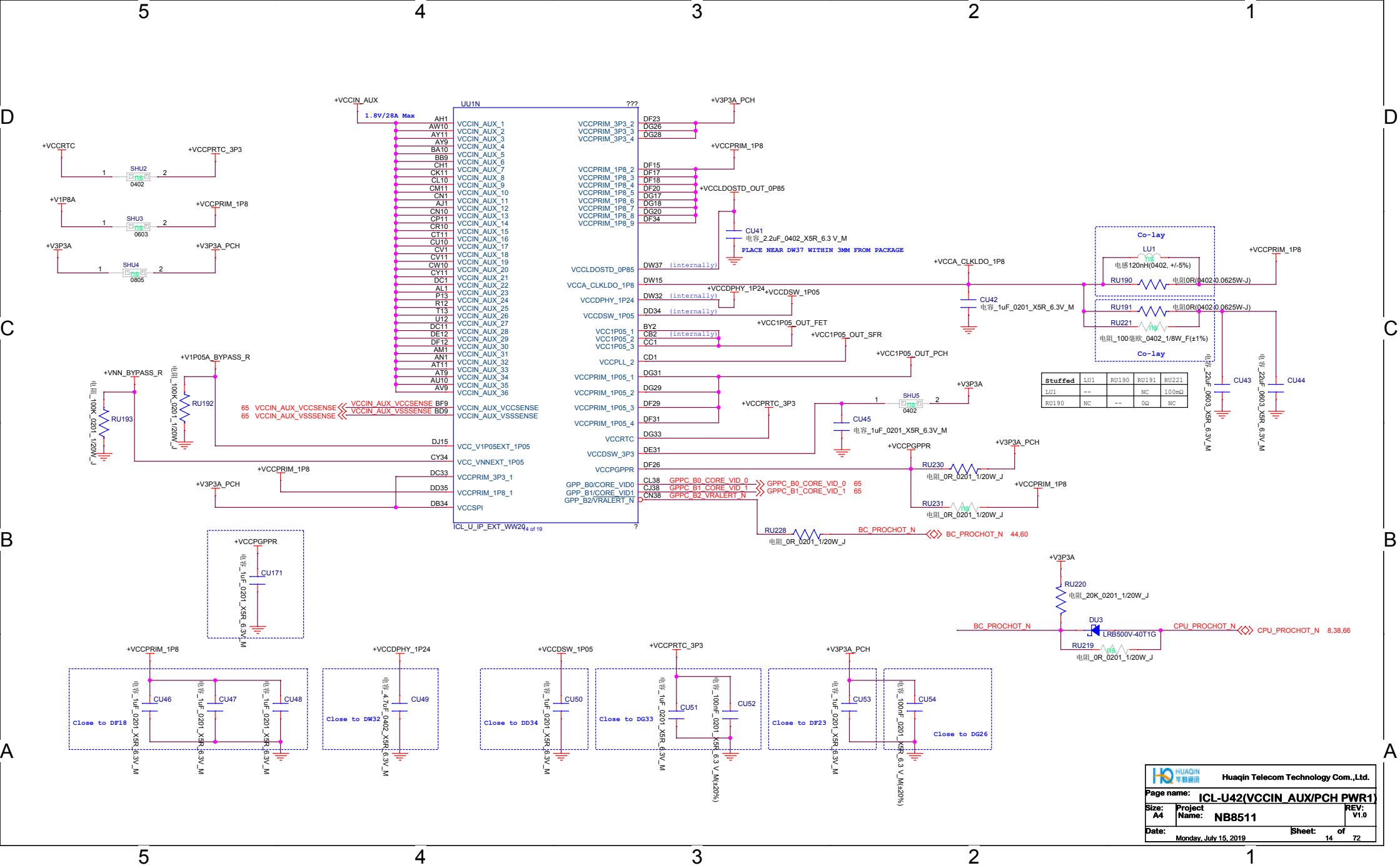


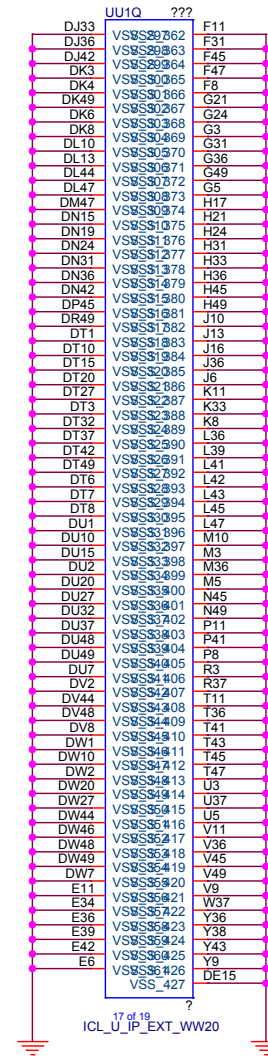
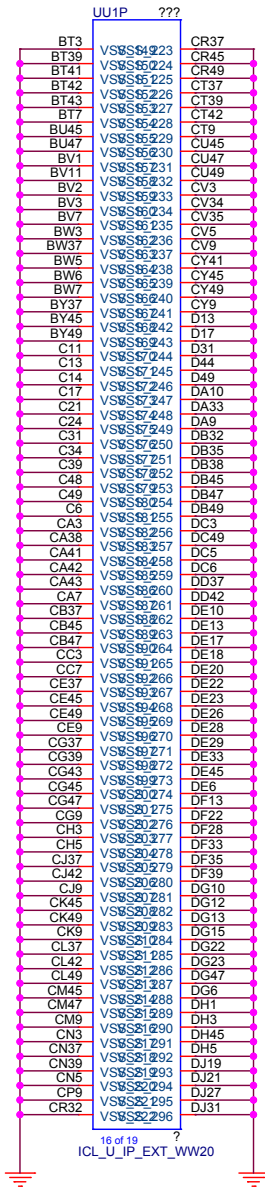
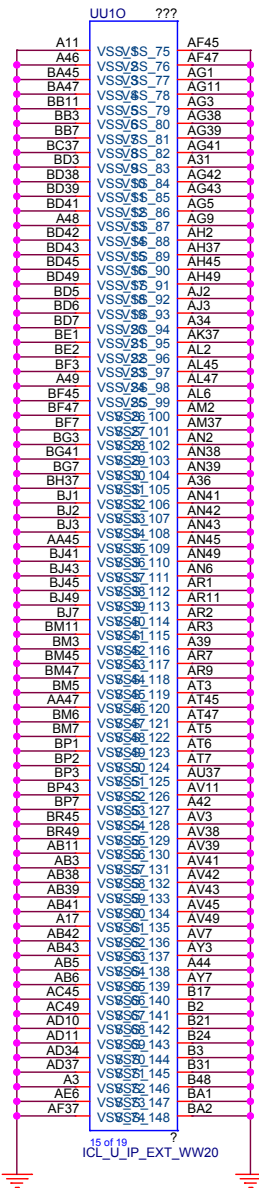
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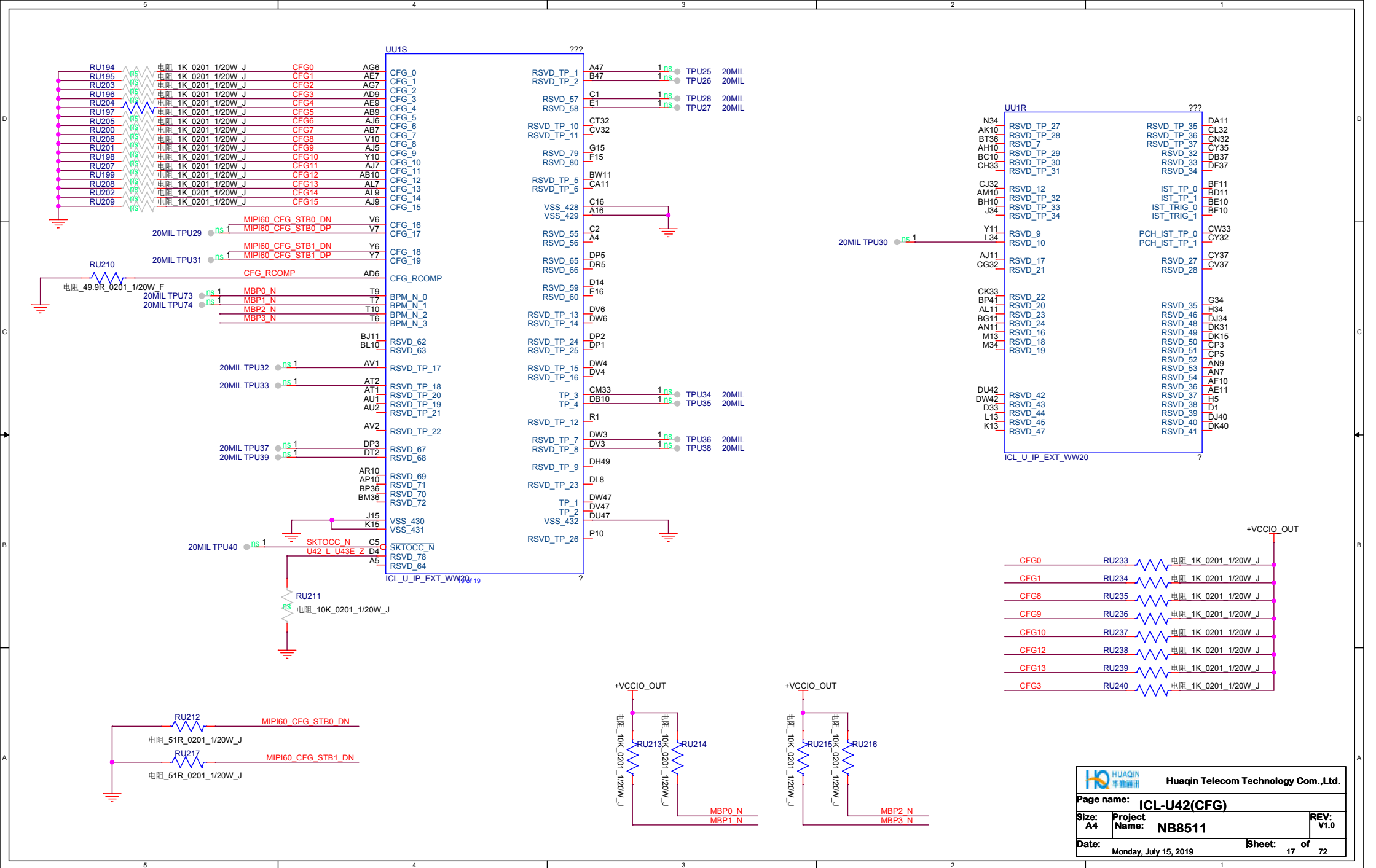


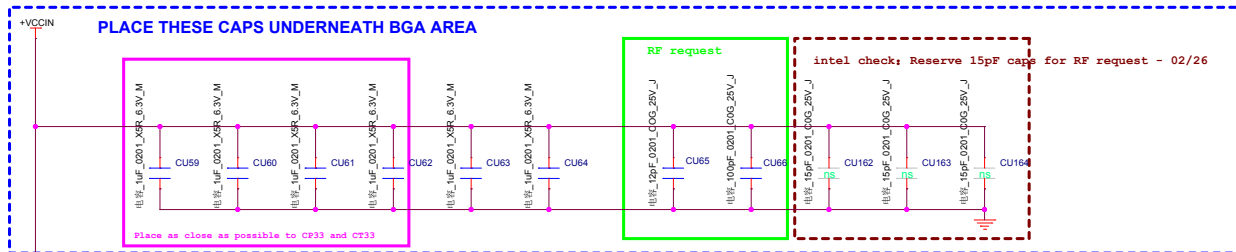
FOR product line





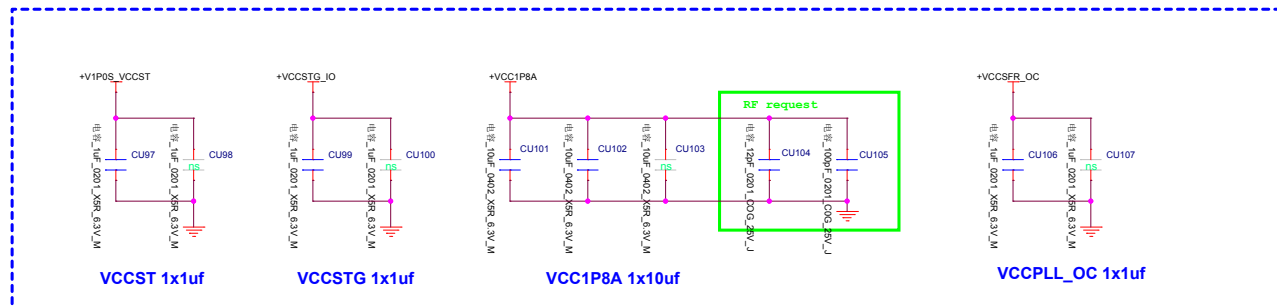
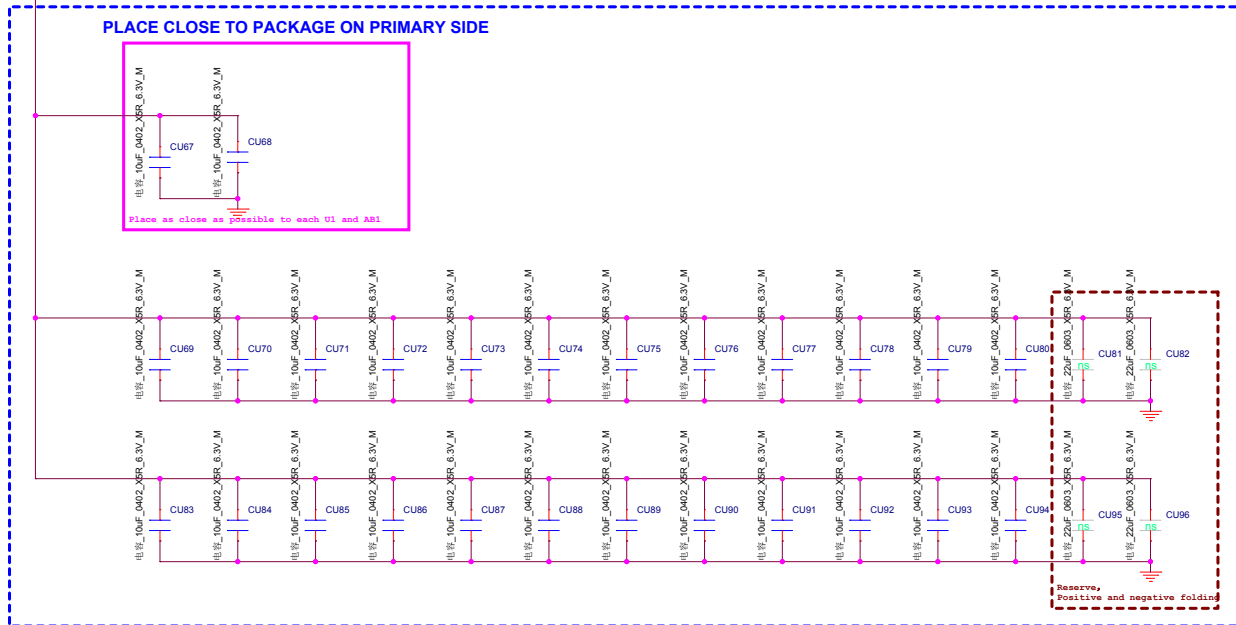


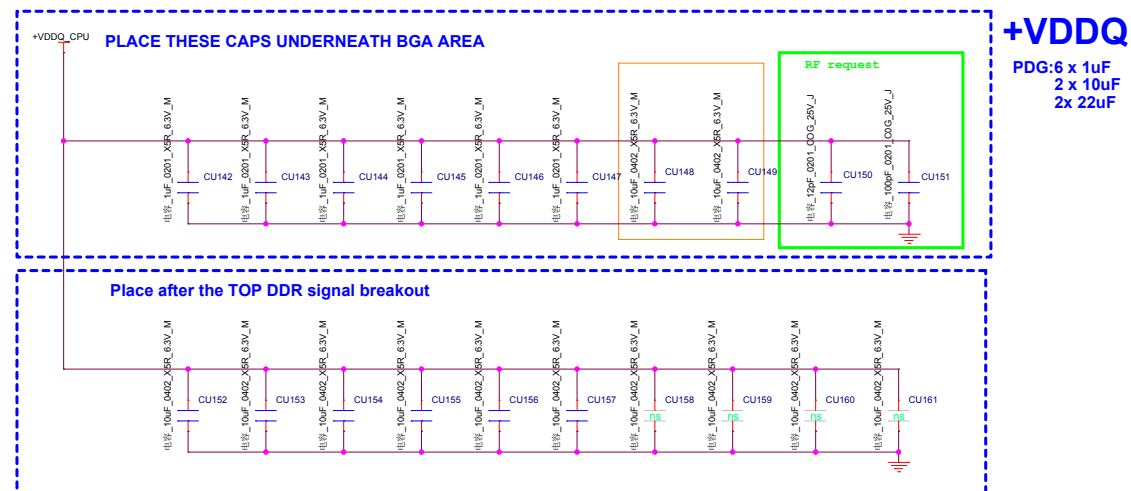
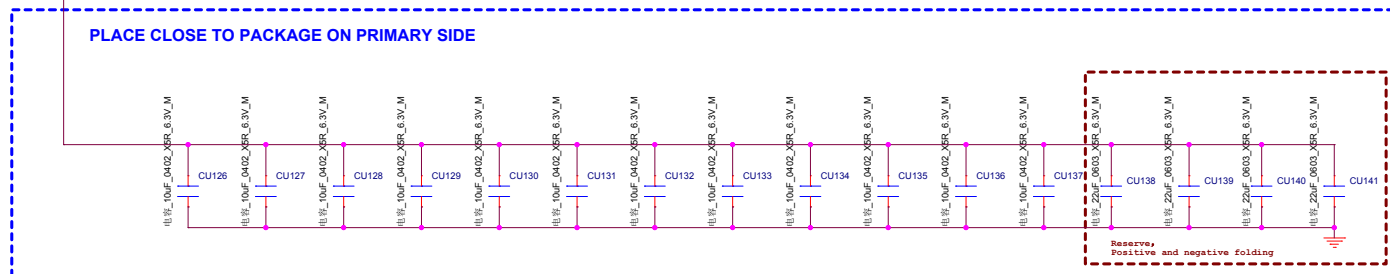
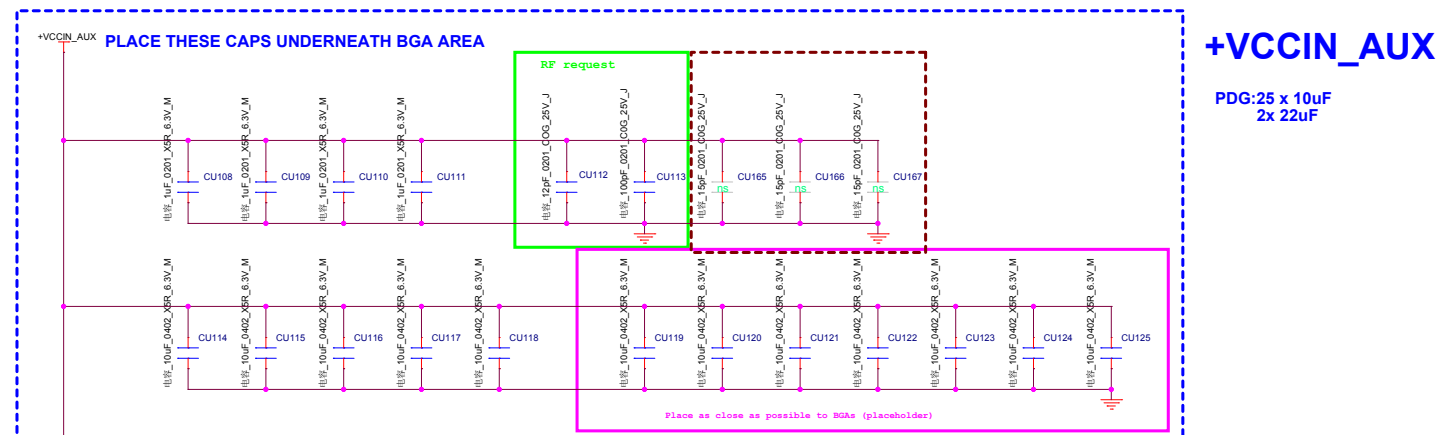


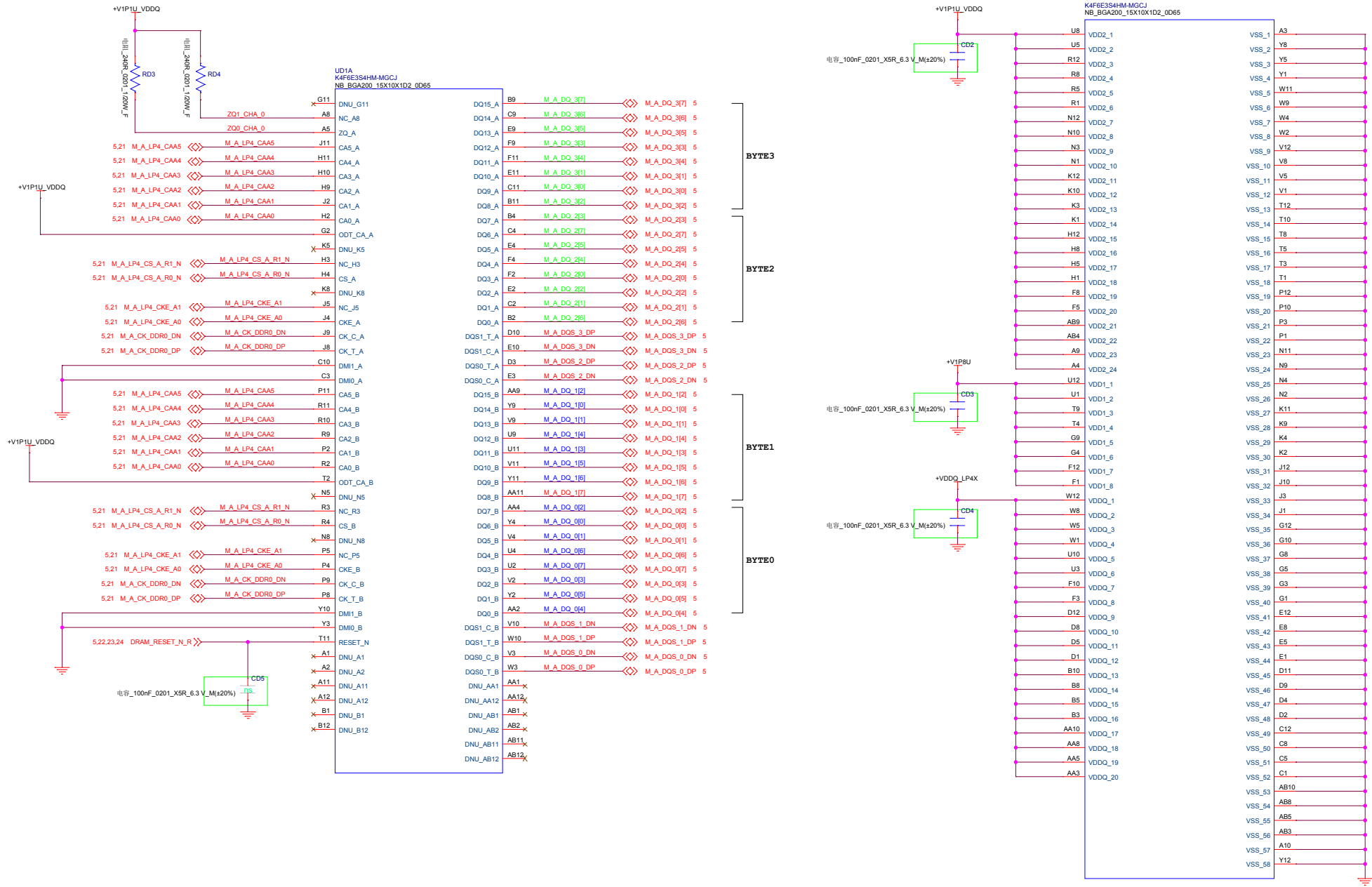


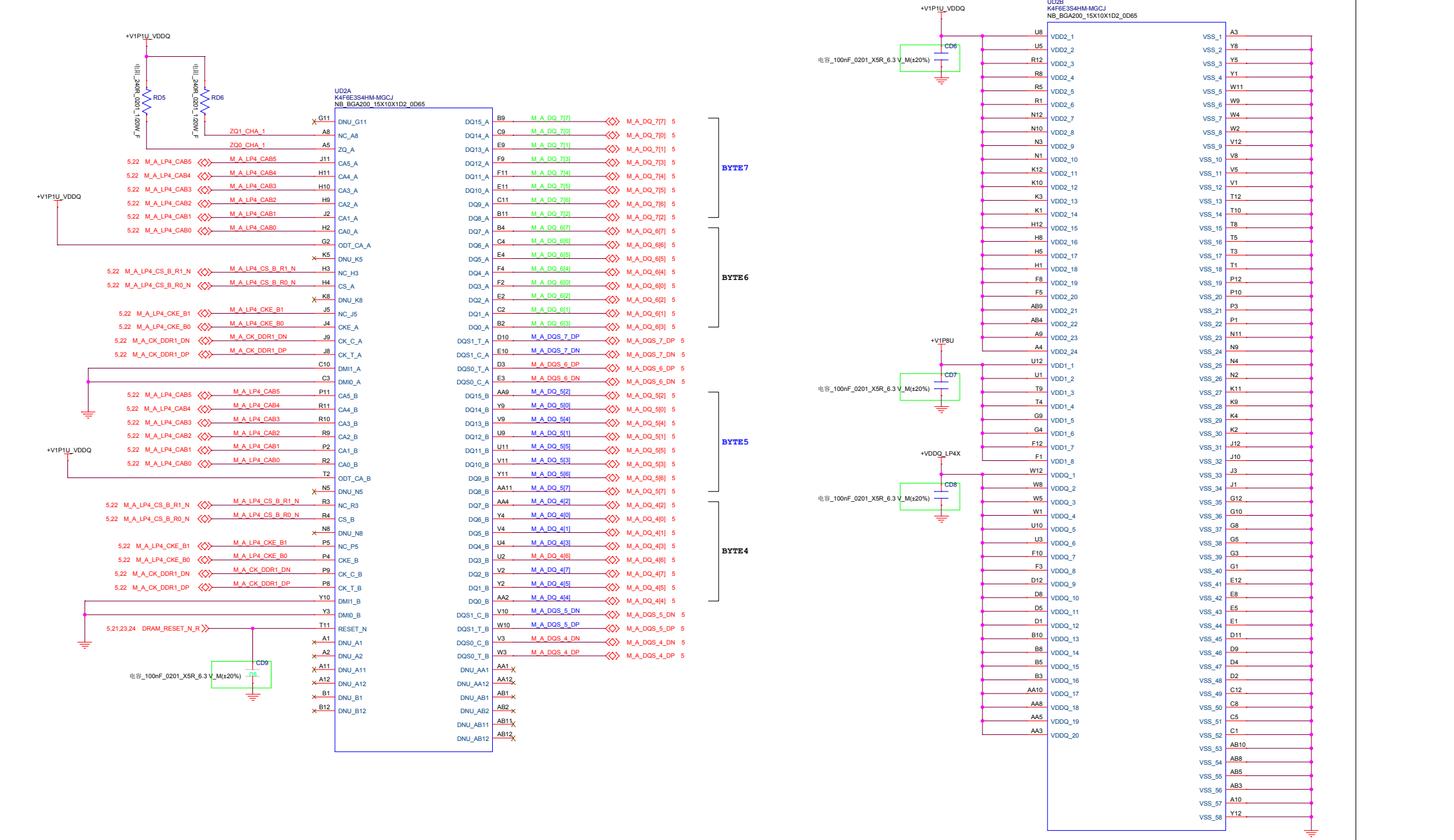
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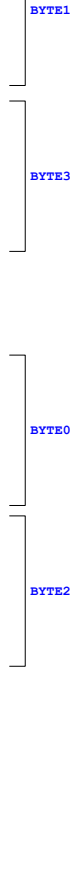
PDG:4 x 1uF
2 x 10uF
10x 22uF
3x 47uF

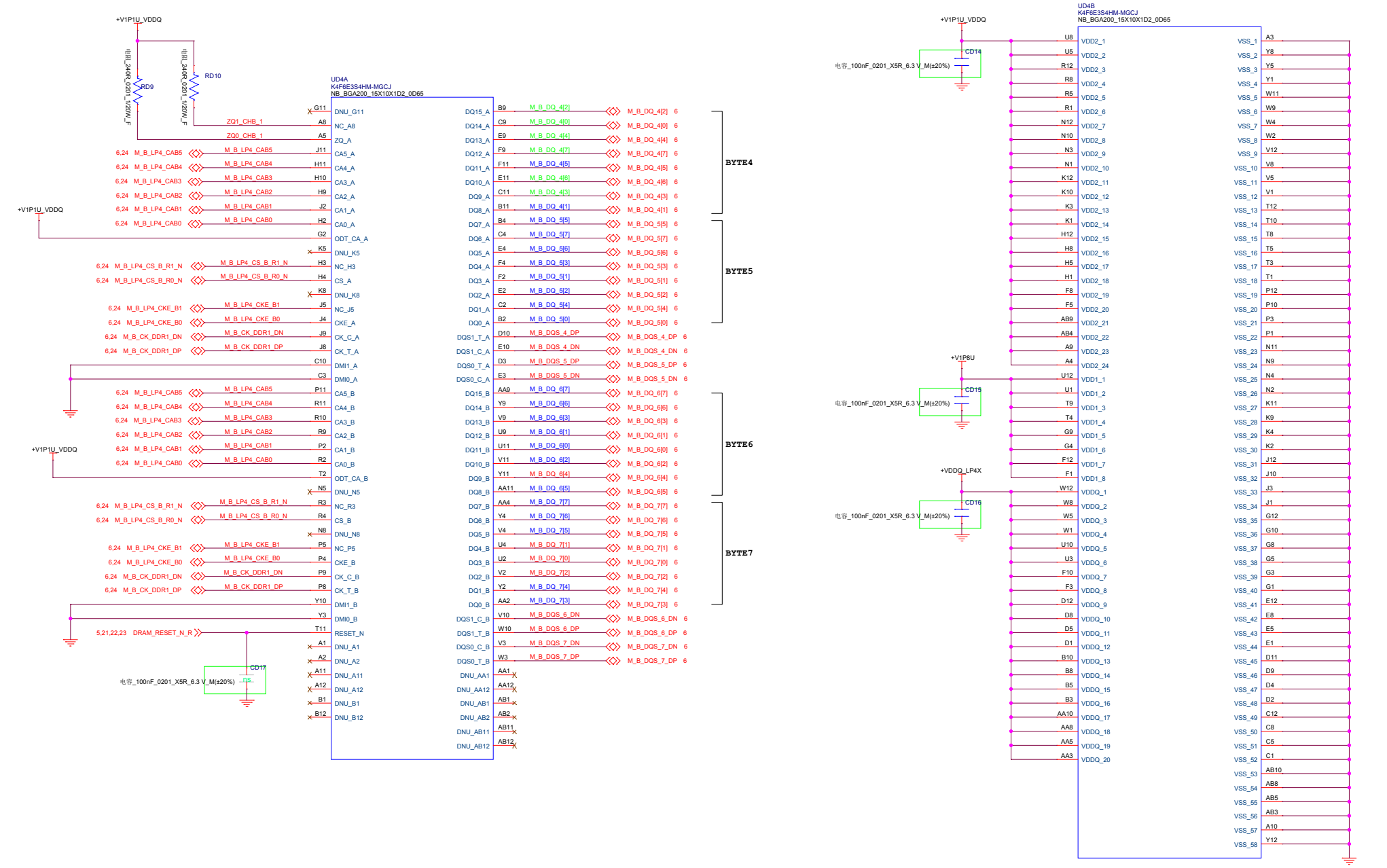






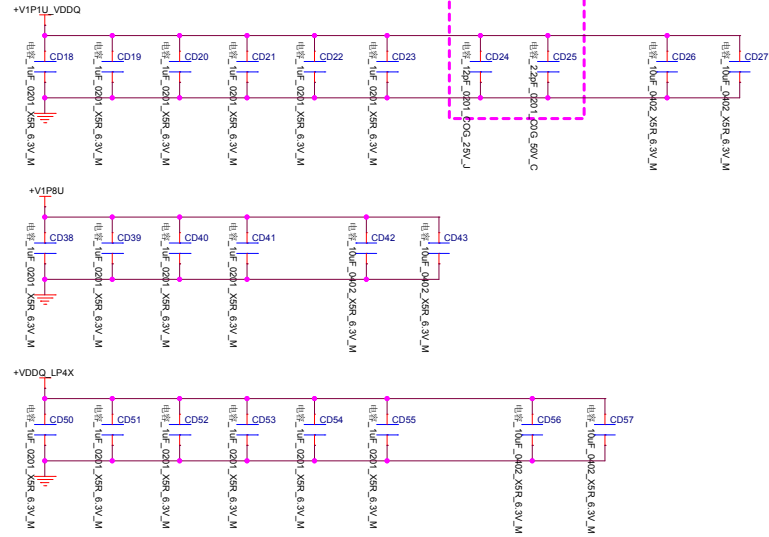




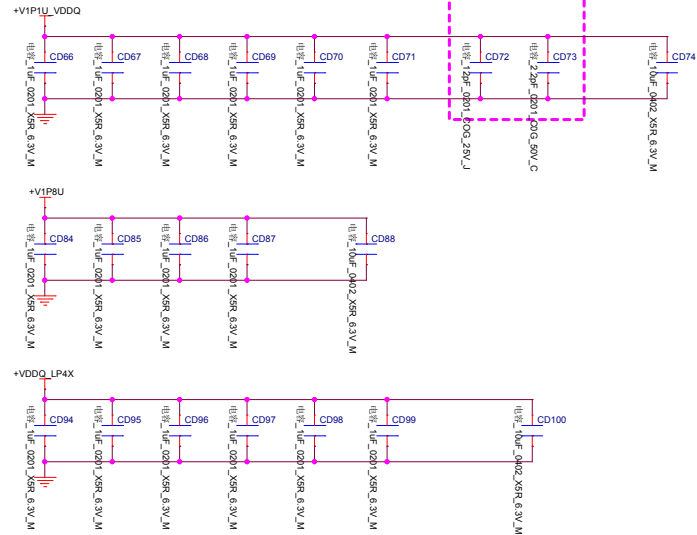


DECOUPLING CAPACITORS FOR LPDDR4 CHANNEL A

Place as close as possible to UD?

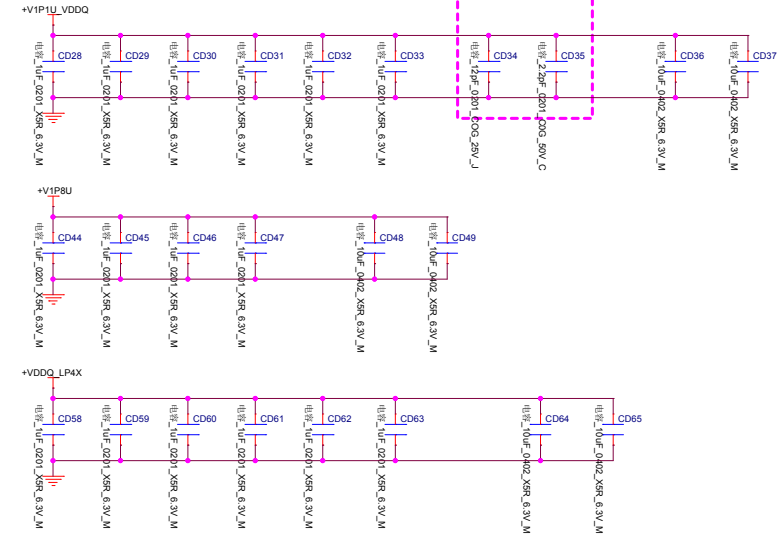


Place as close as possible to UD?

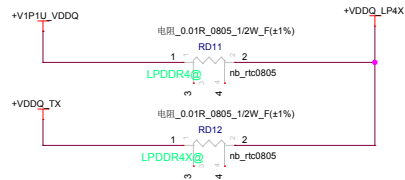
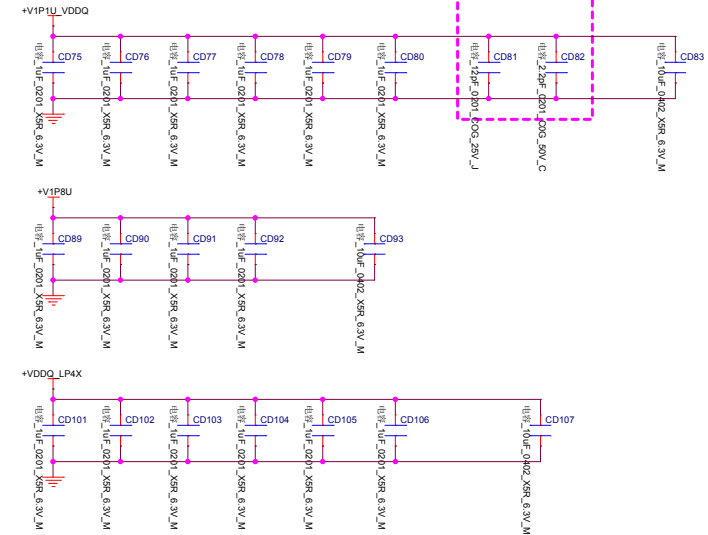


DECOUPLING CAPACITORS FOR LPDDR4 CHANNEL B


Place as close as possible to UD?



Place as close as possible to UD?



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C				C
B				B
A				A
5	4	3	2	1

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D					
C					
B					
A					
	5	4	3	2	1

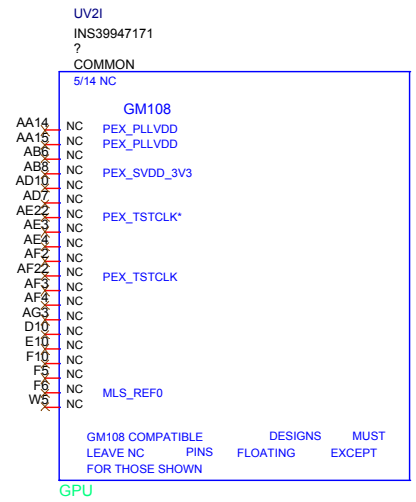
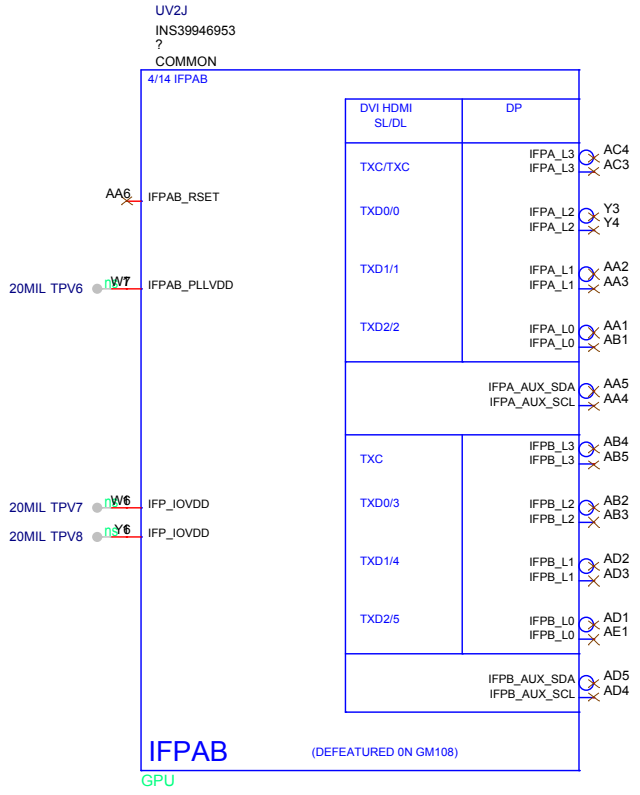
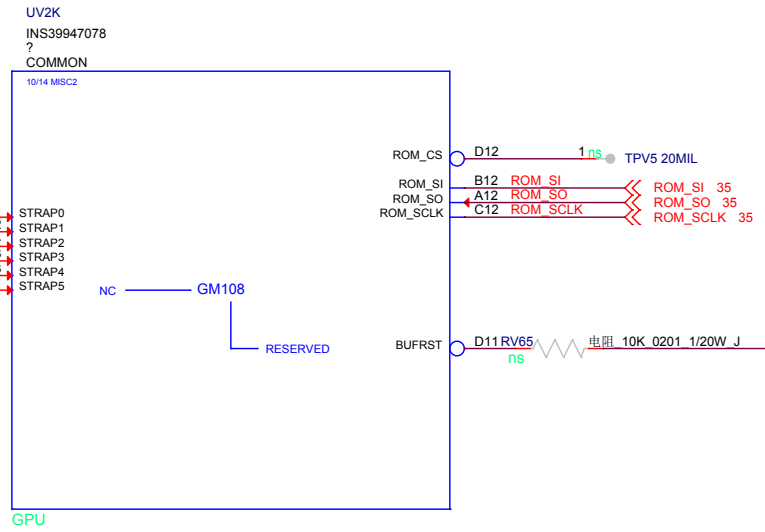
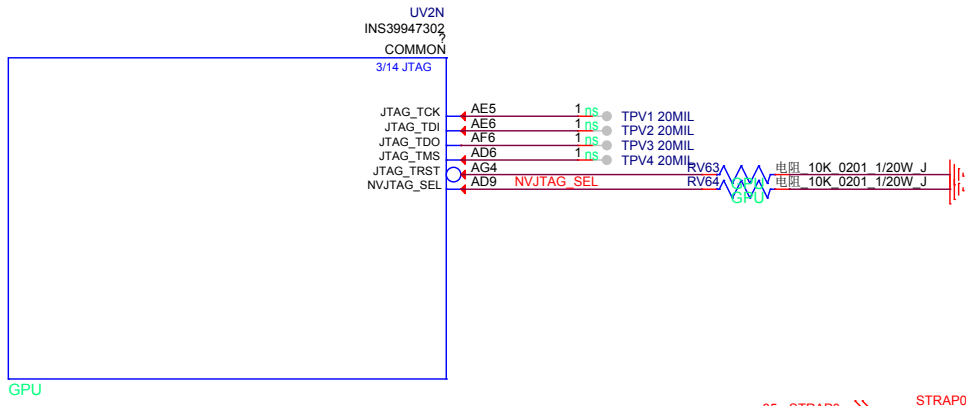


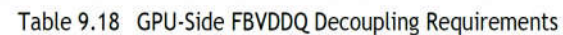
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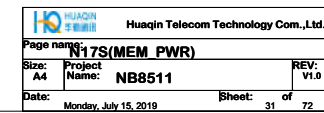






FBVDDQ Decoupling Requirements		
	Recommended Quantity and Placement (for all supported partitions combined)	
Size	Quantity	Placement
2C-64 (preliminary)		
6S [0402]	8	Under GPU FBVDDQ ball (evenly distributed throughout partition)
6S [0603]	2	
6S [0603]	1	Near GPU device
6S [0603]	3	
4C-128 (preliminary)		
6S [0402]	12	Under GPU FBVDDQ ball (equally distributed across partitions)
6S [0603]	4	
6S [0603]	2	Near GPU device
6S [0603]	5	
B4-256		
6S [0402]	24	Under GPU FBVDDQ ball (equally distributed across partitions)
6S [0603]	5	
6S [0603]	7	Near GPU device
6S [0603]	9	

Move to Power Page 2018/06/07



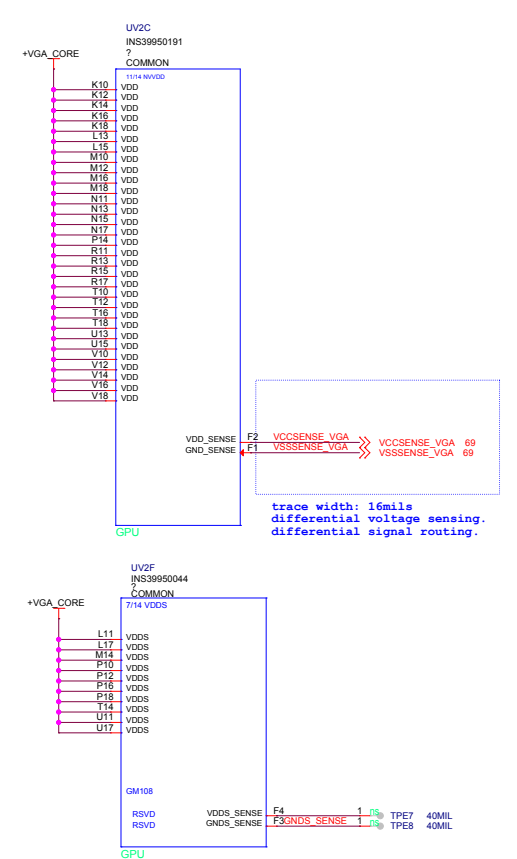
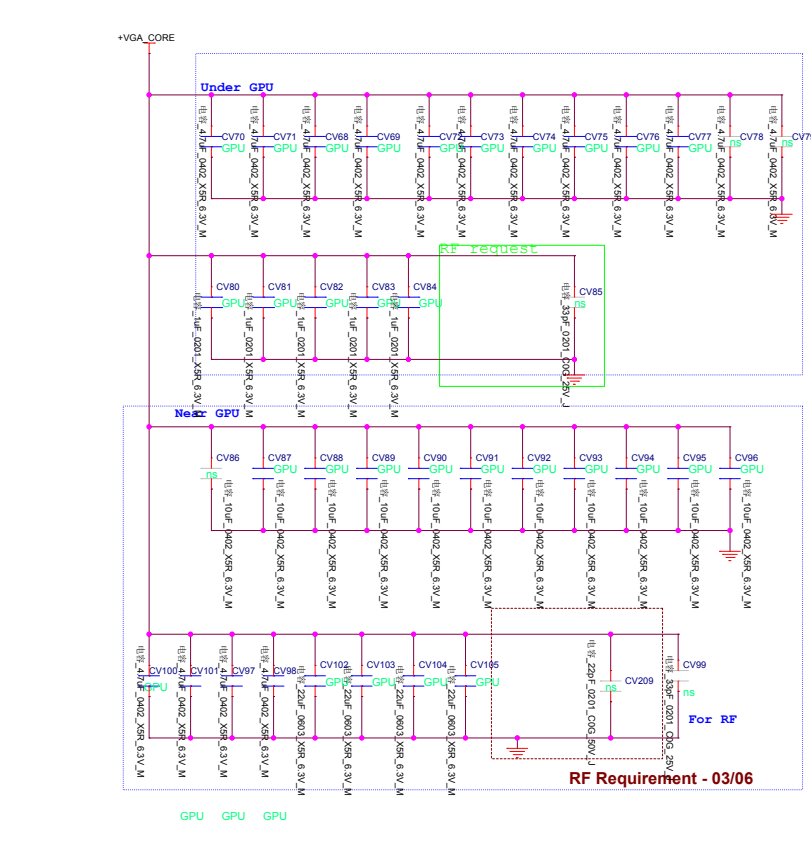
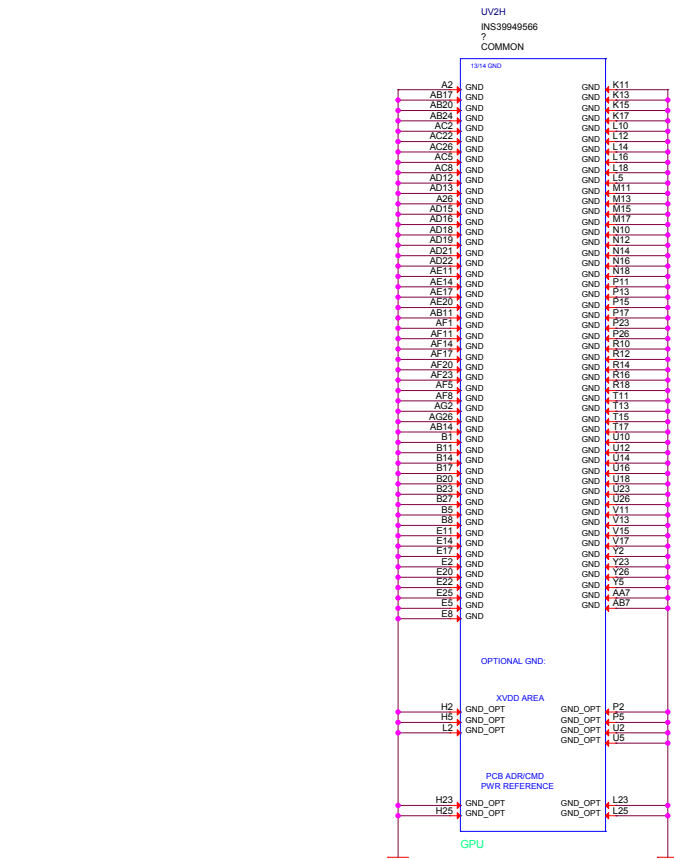


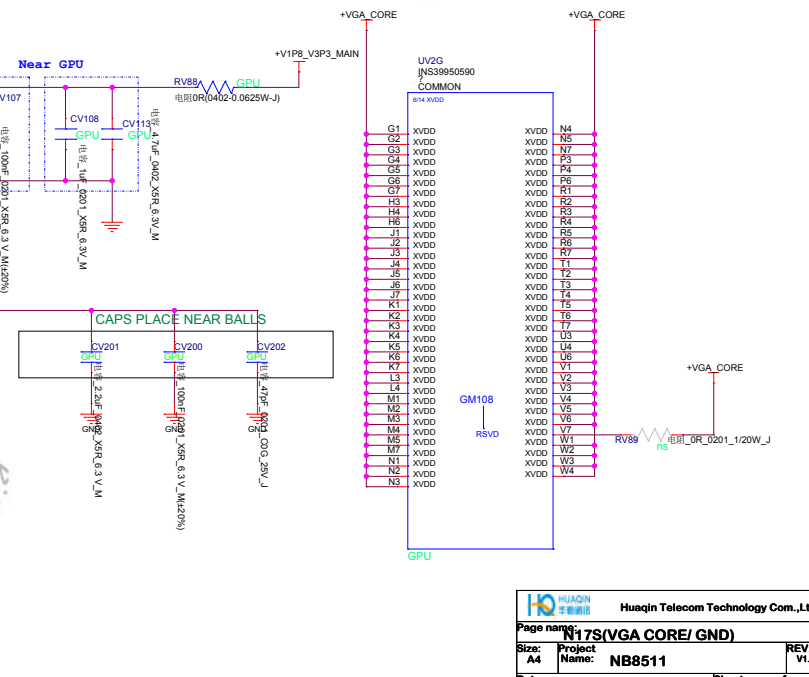
Table 7.18 GB2C-64 Package: Power Rail Filtering

Rail (GPU Ball) Name	Balls	Voltage: Current	Filtering under GPU	Filtering Near GPU
NVDD	31	Varies	3 X 1uF (0402) 8 X 4.7uF (0603)	1 X 4.7uF (0805) 4 X 10uF (0805) 3 X 22uF (0805) 1 X 330uF (Pocap) Near VR: 2 X 10uF (0805)
NVDD05	10	Varies	2 X 1uF (0402) 4 X 4.7uF (0603)	7 X 10uF (0805) 1 X 22uF (0805) 1 X 330uF (Pocap)
FBVDDQ (GPU side) ¹	27	1.35V 1.5V 1.55V	8 X 1uF (0402) 2 X 10uF (0603)	10uF (0603) 3 X 22uF (0603)
FBA_PLL_AVDD	1	1.8V	2 X 0.1uF (0402 X7R)	1 X 300 bead (0603 max<ESR 10 mΩ)
FBB_PLL_AVDD	1	1.8V	0.1uF (0402 X5R)	1 X 22uF (0805)
FB_REFPLL_AVDD	1	1.8V	1 X 0.1uF (0402 X5R)	1 X 300 bead (0603 max<ESR 0.01 Ω)
IFPAB_PLLVDD	1	1.8V	2 X 0.1uF (0402 X5R)	1 X 4.7uF (0402)
GPCPLL_AVDD	2	1.8V	1 X 0.1uF (0402 X5R)	1 X 4.7uF (0402)
XS_PLLVDD	1	1.8V	1 X 0.1uF (0402 X5R)	1 X 4.7uF (0402)
SP_PLLVDD	1	1.8V	1 X 0.1uF (0402 X5R)	1 X 4.7uF (0402)
WD_PLLVDD	1	1.8V	1 X 0.1uF (0402 X5R)	1 X 4.7uF (0402)
IFP_OVDD	2	1.0V	2 X 0.1uF (0402 X65)	1 X 4.7uF (0402)

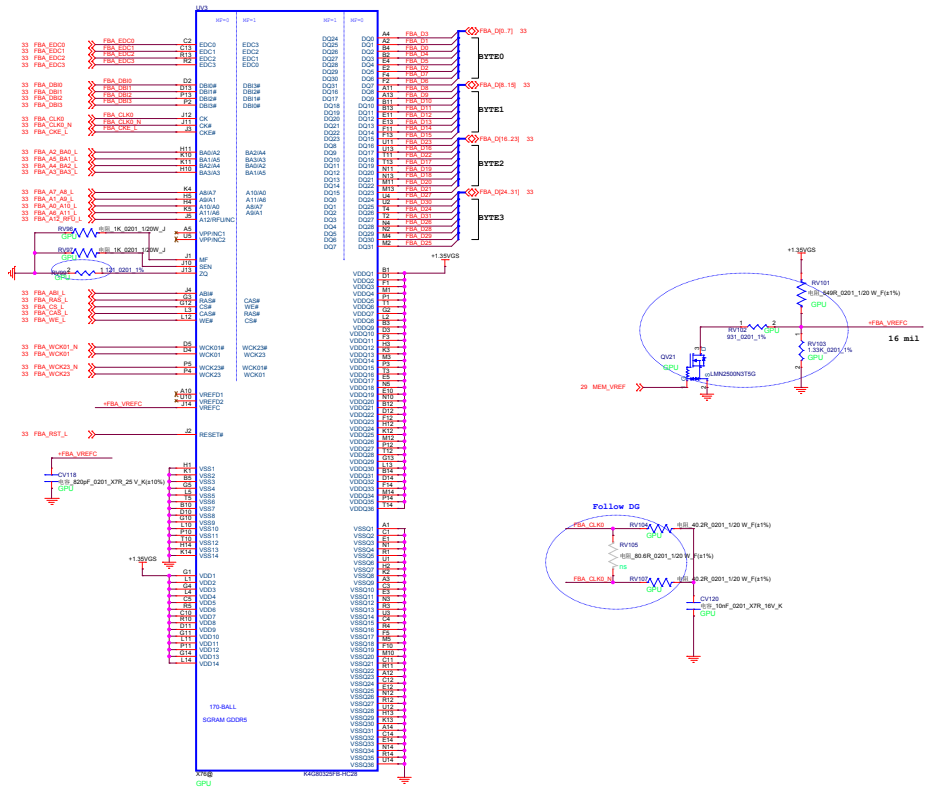
Table 7.18 GB2C-64 Package: Power Rail Filtering (Continued)

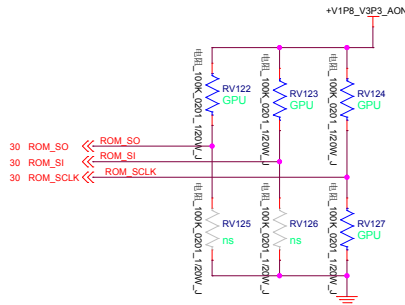
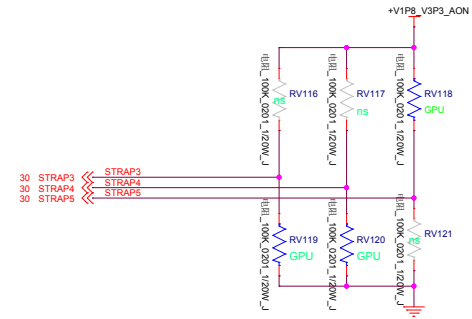
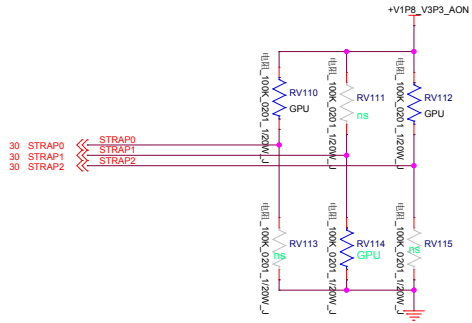
Rail (GPU Ball) Name	Balls	Voltage: Current	Filtering under GPU	Filtering Near GPU
PEX_HVDD	14	1.8V	4 X 1uF (0402 X5R)	Near GPU: 2 X 4.7uF (0603) Midway bet GPU & VR: 2 X 10uF (0805) 1 X 22uF (0805)
PEX_HVDD0	2	1.8V	1 X 0.1uF (0402)	Near GPU: 2 X 4.7uF (0603) Midway bet GPU & VR: 2 X 10uF (0805) 1 X 22uF (0805)
PEX_DVDD	6	1.0V	2 X 1uF (0402 X5R)	Near GPU: 2 X 4.7uF (0603) Midway bet GPU & VR: 2 X 10uF (0805) 1 X 22uF (0805)
1V8_MAIN	2	1.8V	2 X 0.1uF (0402)	1 X 1uF (0402)
1V8_AON	2	1.8V	2 X 0.1uF (0402)	1 X 1uF (0402)

Note:
1. Also see Section 9.2.2.1.10.1



Memory - Lower 32 bits





For N17

GPU	Vendor	Manufacturer	Strap	Strap2	Strap1	Strap0
N17S-G1	Samsung	K4G80325FB-HC28	0x0	L	L	L
	Micron	MT51J256M32HF-70:A	0x1	L	L	H
	Hynix	H5GC8H24MJR-ROC	0x2	L	H	L
	Micron	MT51J256M32HF-70:B	0x4	H	L	L
N17S_G0/G2	Hynix	H5GC8H24AJR-ROC	0x5	H	L	H
	Micron	MT51J256M32HF-80:B	0x9	L	M	L
	Hynix	H5GC8H24AJR-R2C	0xA	L	M	H

PN	MPN	STRAP	Vendor
HQ1121499000	K4G80325FB-HC28	0x00	Samsung
HQ1121497000	H5GQ8H24MJR-R4C	0x02	Hynix

Physical Strapping pin	Power Rail	RAM_CFG[3]	RAM_CFG[0x02]	RAM_CFG[1]	RAM_CFG[0x00]
STRAP0			L		L
STRAP1			H		L
STRAP2			L		L

SMBUS	ALT	ADDR
0		0x9E (Default)
1		0x9C (Multi-GPU usage)

DEVID	SEL
0	(Default)
1	

PCIE	CFG
0	(Default)
1	

VGA	DEVICE
0	3D Device (Class Code 302h)
1	VGA Device (Default)

Physical Strapping pin	Power Rail	SOR3_EXPOSED	SOR2_EXPOSED	SOR1_EXPOSED	SOR0_EXPOSED
ROM_SCLK	M				
ROM_S1	H	Disable	Disable	Disable	Disable
ROM_S0	H				

Table 5.3 RAMCFG

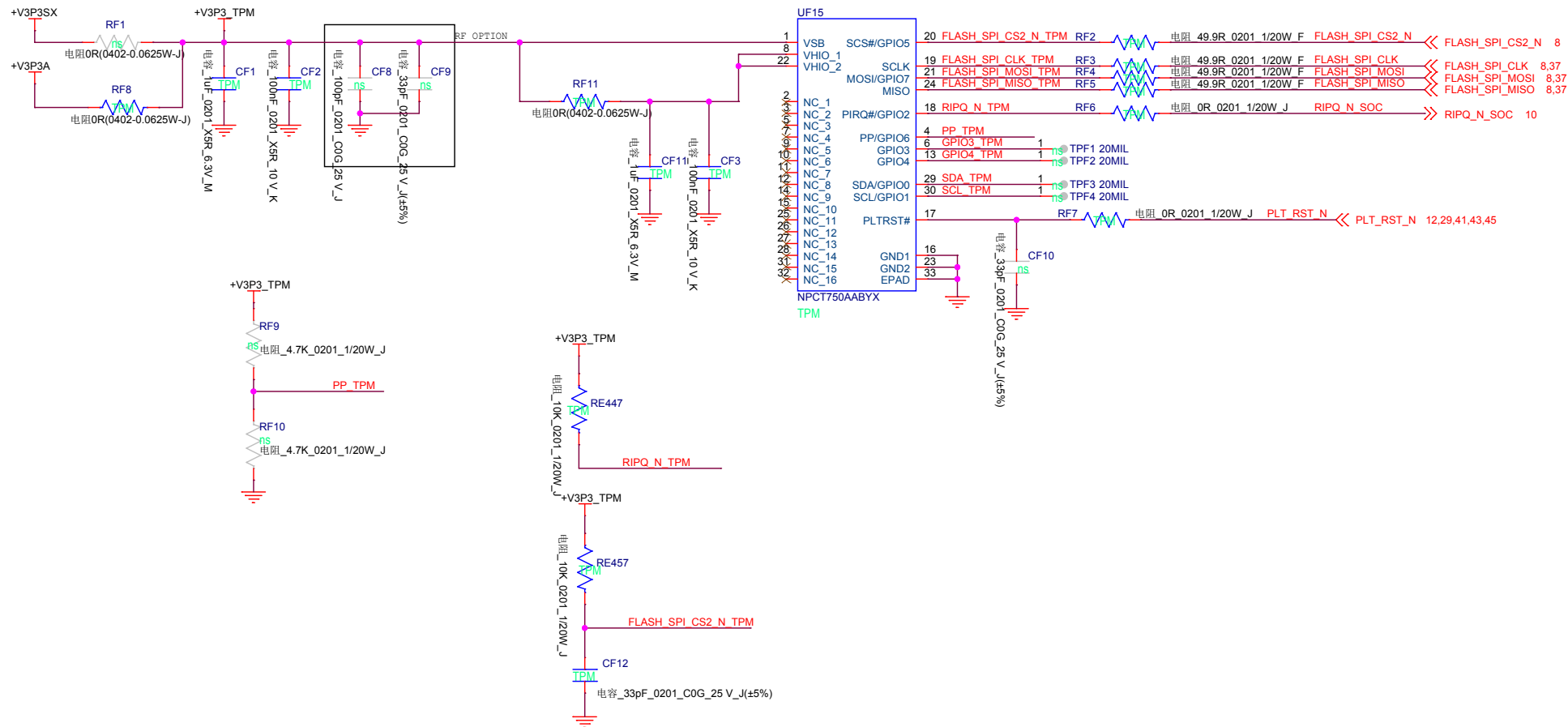
Strap Pins ^{see Note}			RAMCFG Setting Number
STRAP2	STRAP1	STRAP0	(see Memory RVL for memory configs corresponding to these numbers)
L	L	L	0 (0x0000)
L	L	H	1 (0x0001)
L	H	L	2 (0x0002)
L	H	H	3 (0x0003)
H	L	L	4 (0x0004)
H	L	H	5 (0x0005)
H	H	L	6 (0x0006)
H	H	H	7 (0x0007)
L	L	M	8 (0x0008)
L	M	L	9 (0x0009)
L	M	H	10 (0x000A)
L	H	M	11 (0x000B)
M	L	L	12 (0x000C)
M	L	H	13 (0x000D)

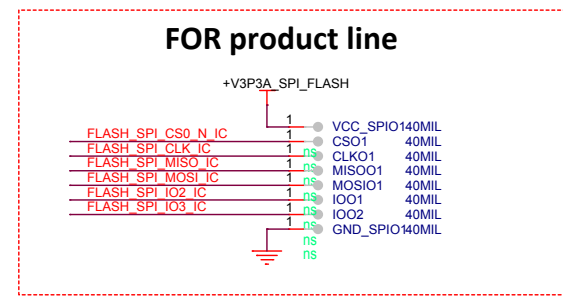
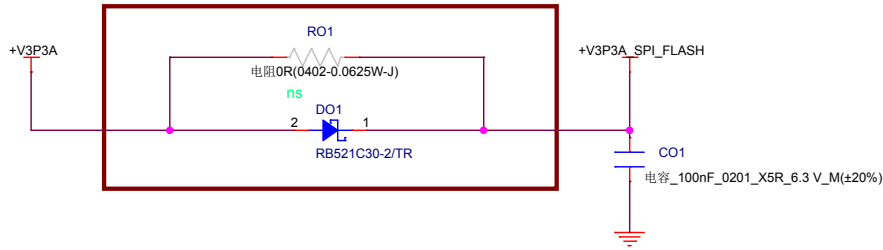
Table 5. N17S-G0/G2 GDDR5 Recommended Memories

Memory Density	Allowed Memory Configuration	FBVDD/Q	Vendor	Manufacturer Part Number	Die Revision	Strap	Memory Speed Grade	Date Code Alert	Qual Plan	Status
8 Gb	256Mx32 512Mx16	1.35V	Micron	MT51J256M32HF-80:B	B-die	0x9	8 Gbps	N/A	Full	Production ready
			Hynix	H5GC8H24AJR-R2C	A-die	0xA	8 Gbps	N/A	Full	Production ready

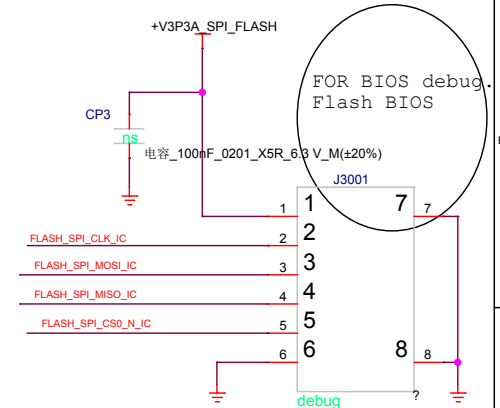
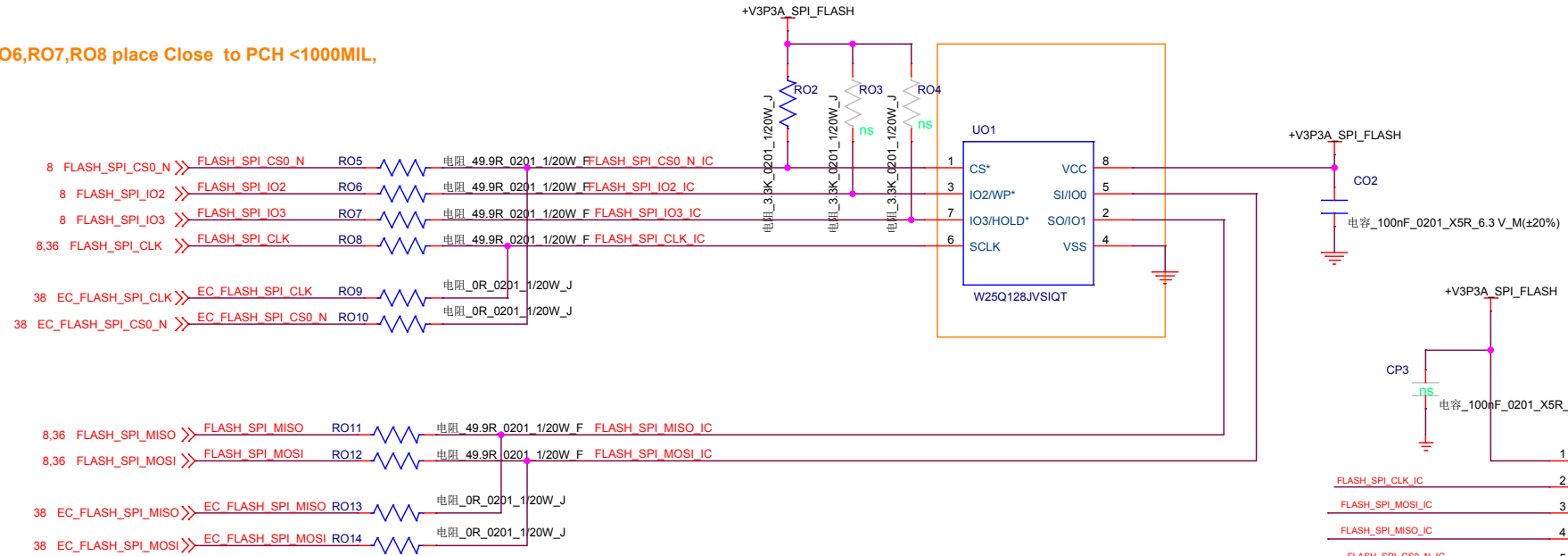
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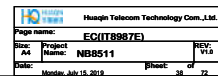
- For N17S-G0/G2, the maximum allowable memory case temperature is 85 °C.
- N17S-G0/G2 running at 3.0 GHz (without intent to run 3.5 GHz at a later stage) can also use the memory configurations in Table 4 for N17S-G1.



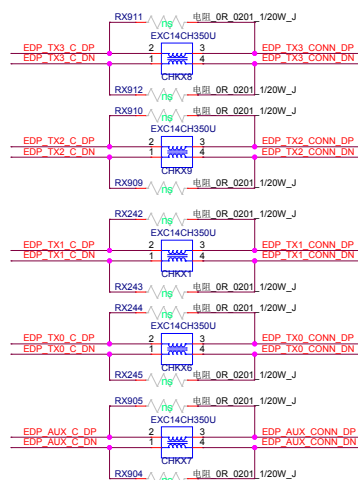
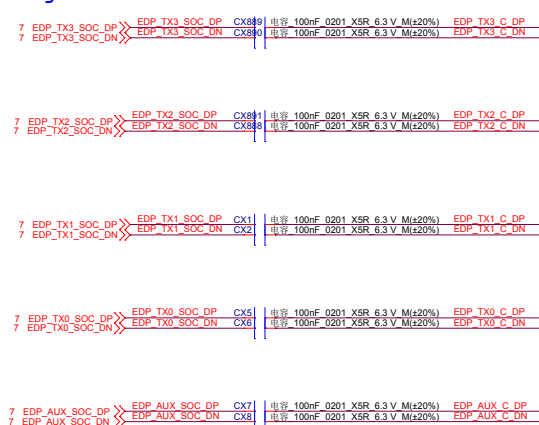


Series RO5,RO6,RO7,RO8 place Close to PCH <1000MIL,

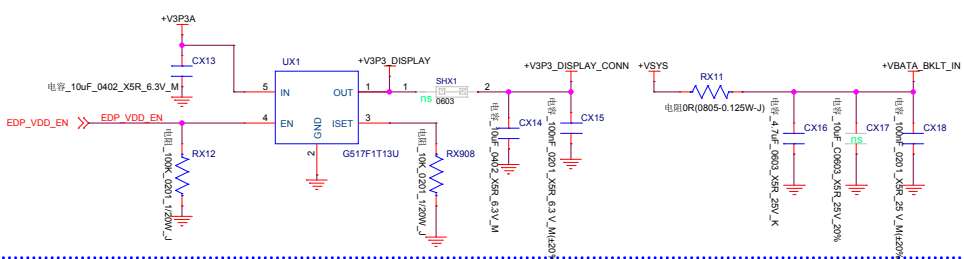




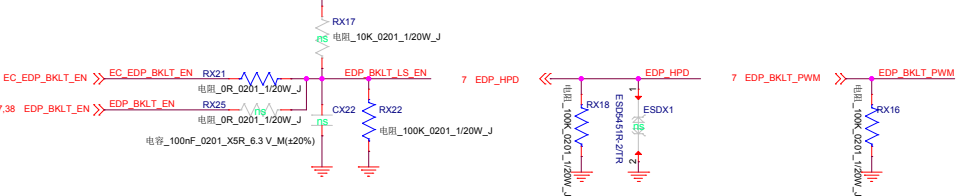
eDP Signal



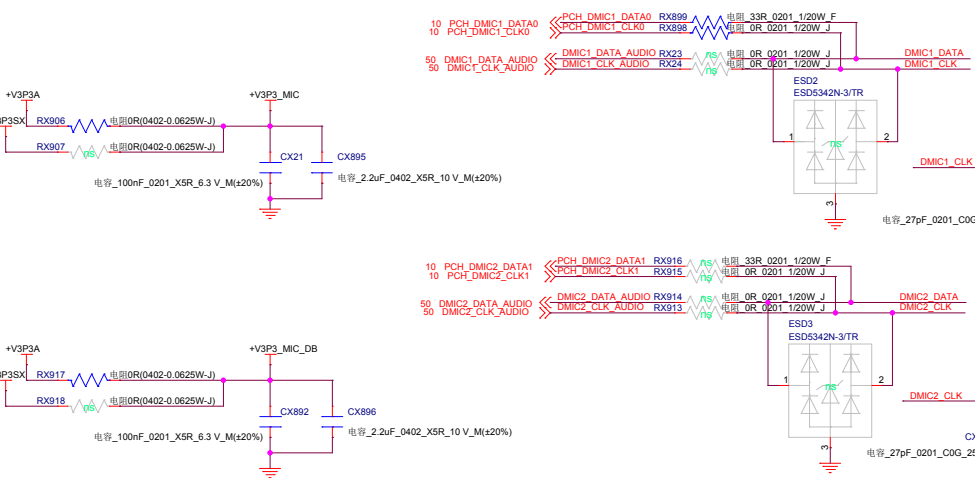
eDP VCC & BL Power



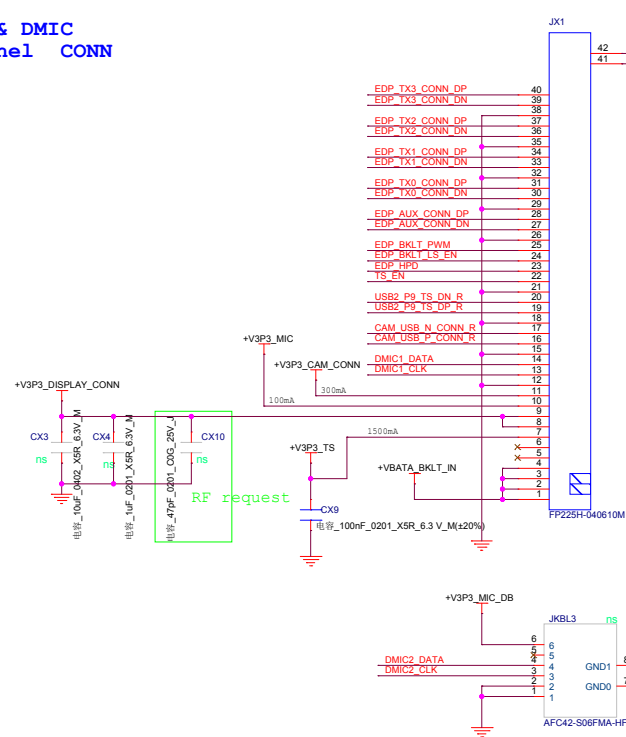
eDP Control



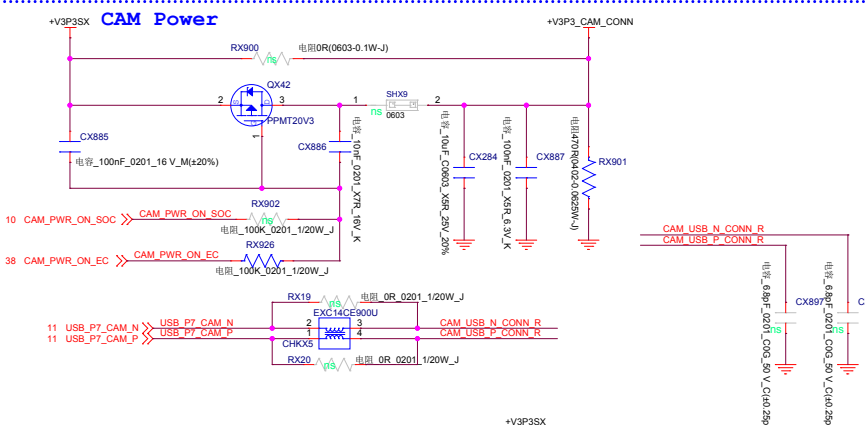
MIC



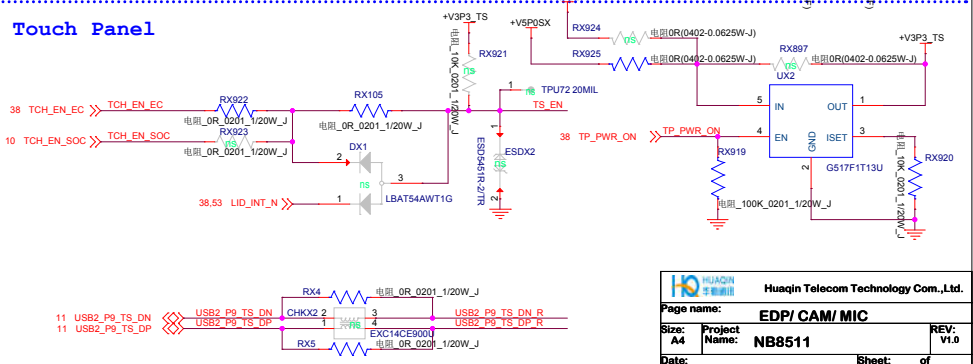
eDP & CAM & DMIC
& Touch Panel CONN



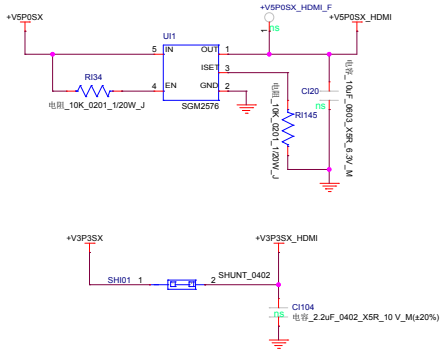
CAM Power



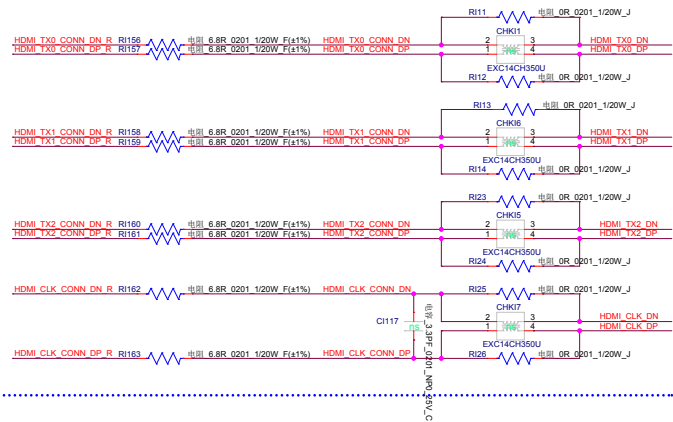
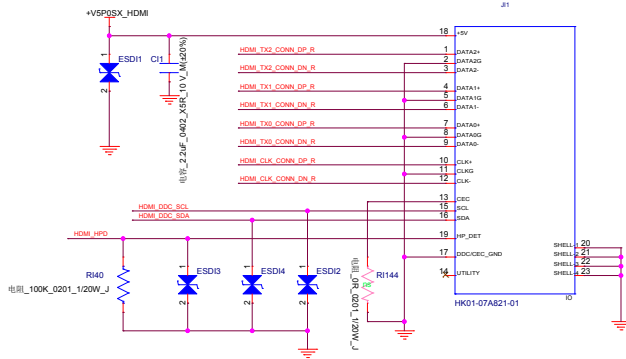
Touch Panel



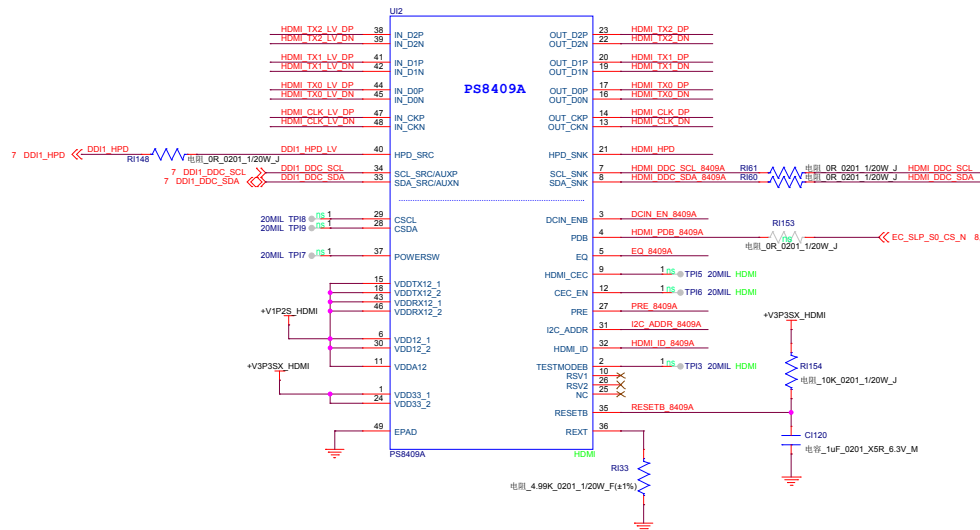
Power 1



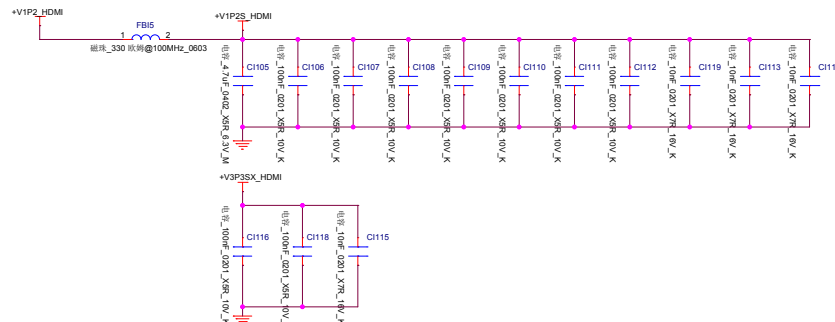
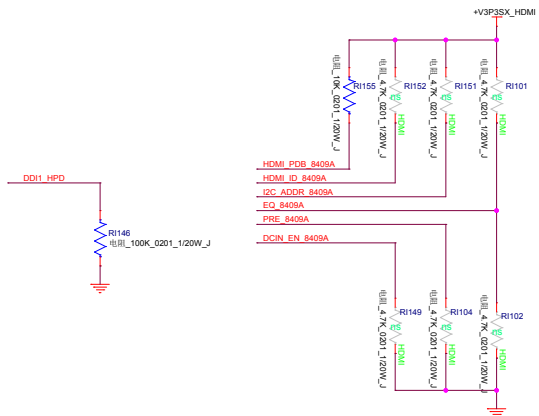
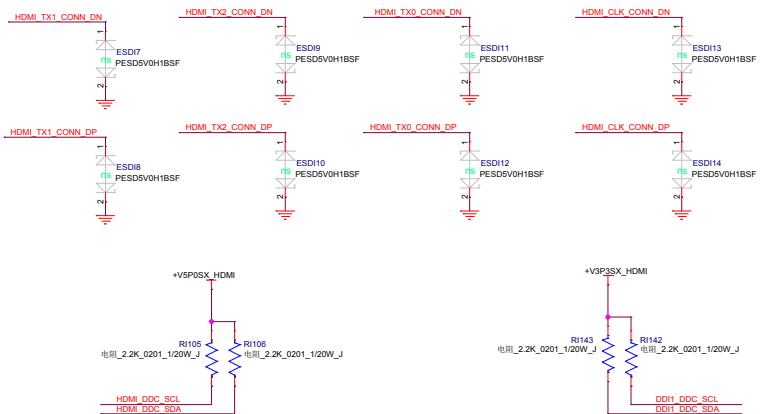
HDMI CONN



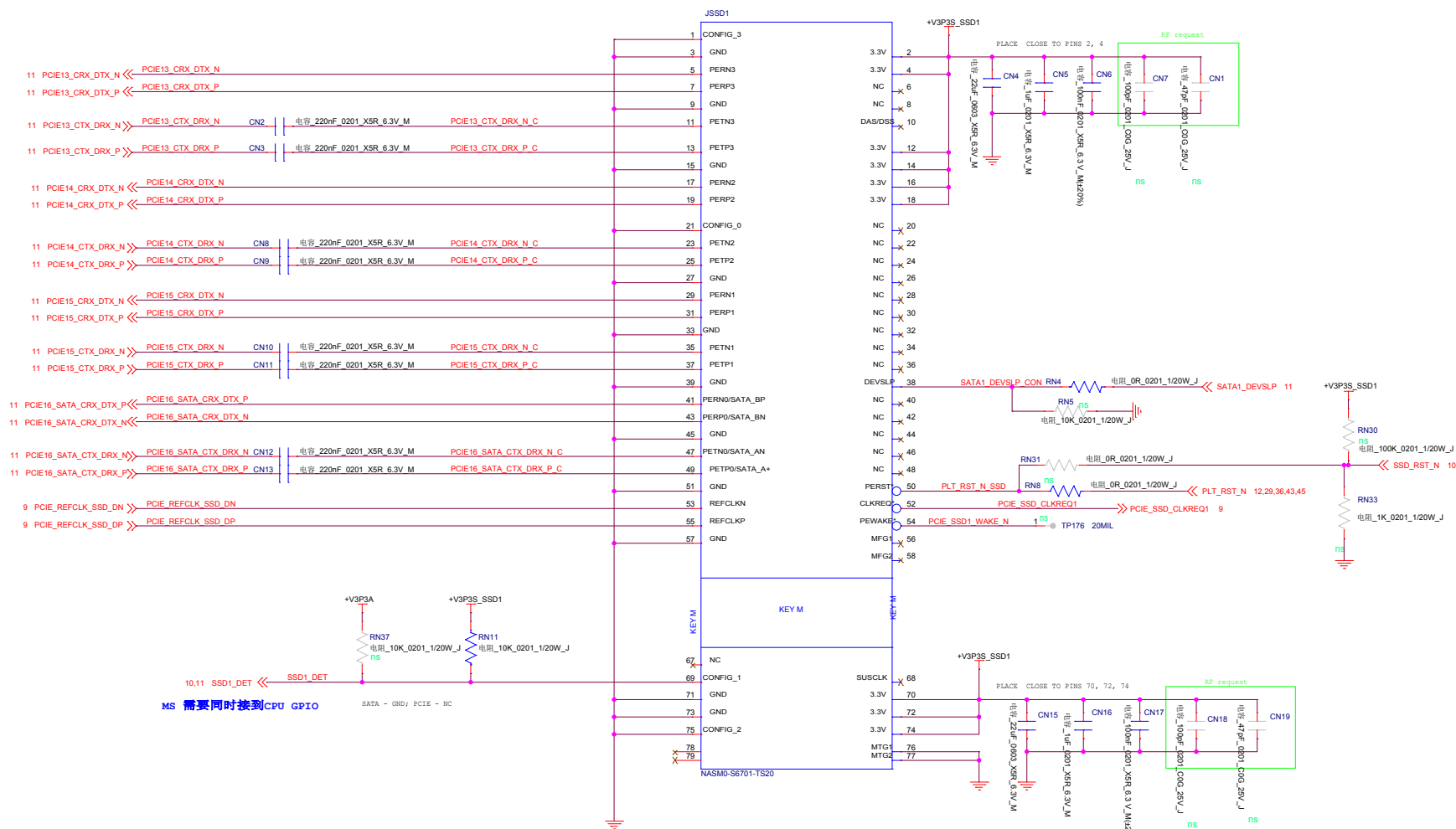
Signal

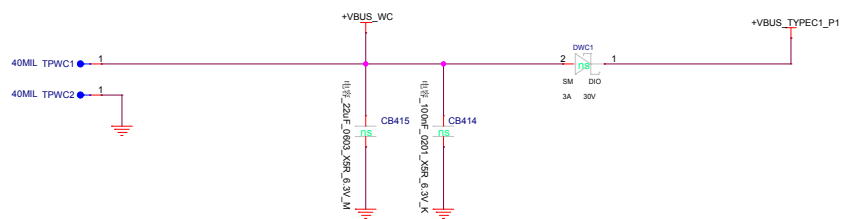


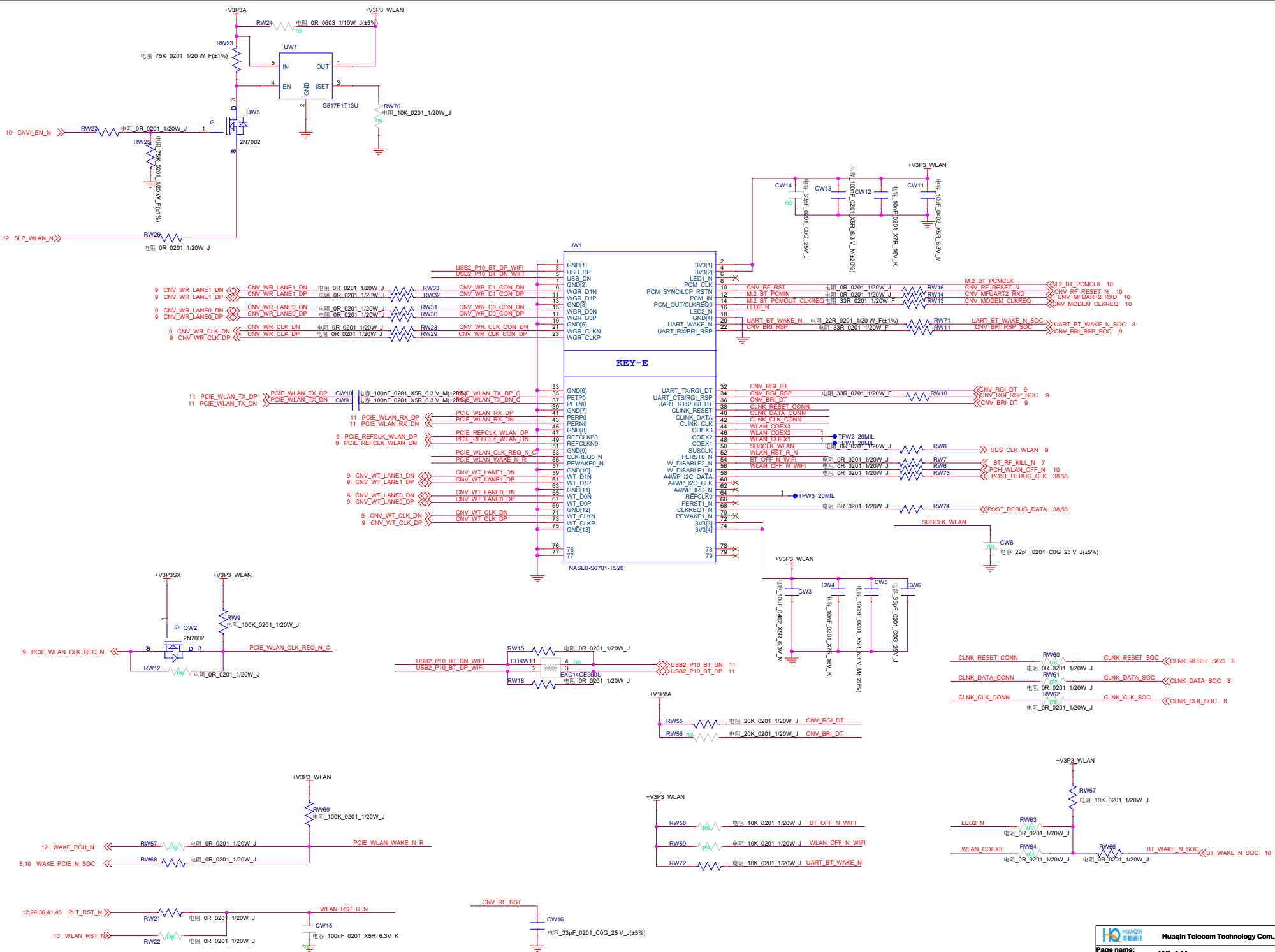
ESD

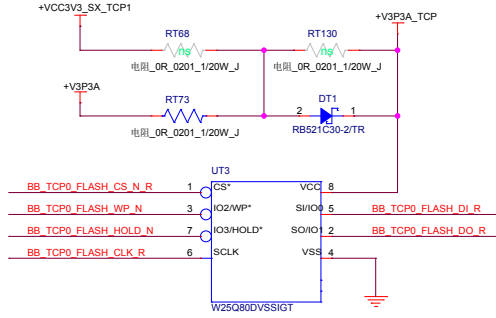
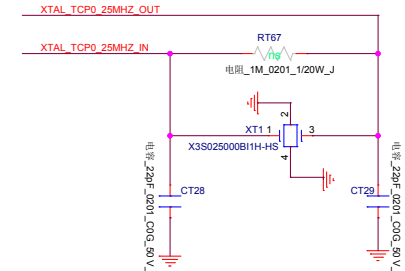
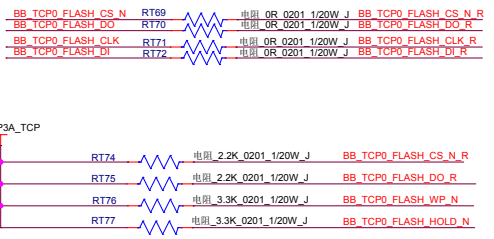
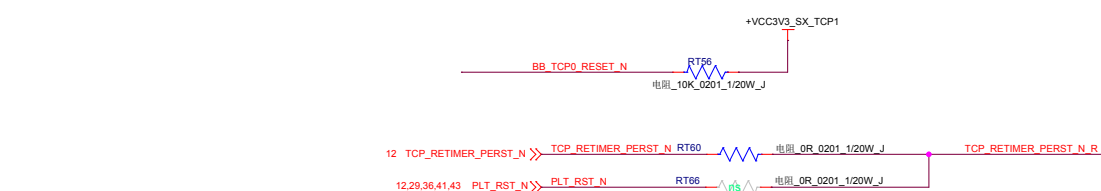
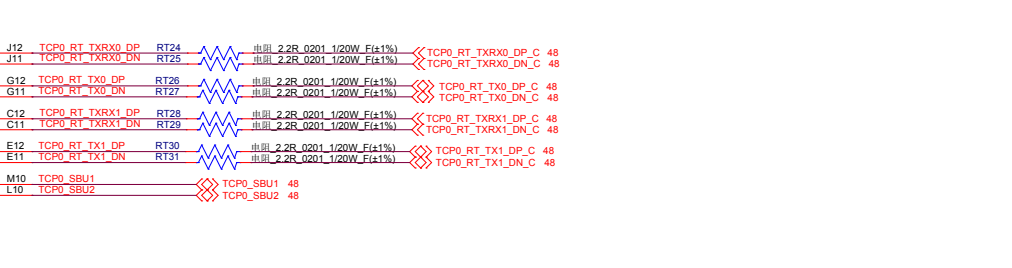


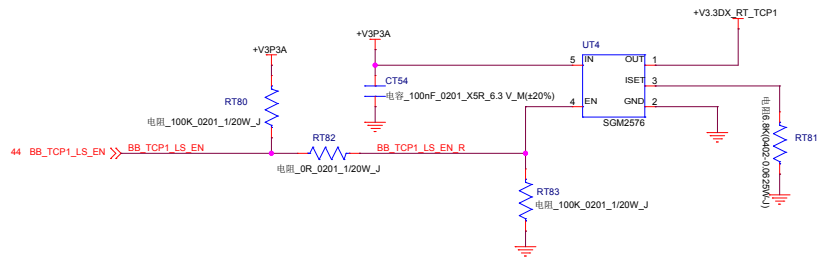
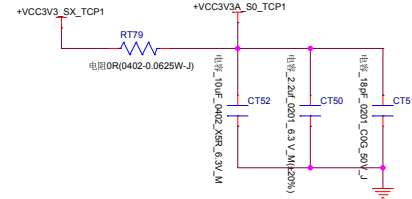
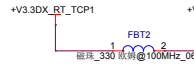
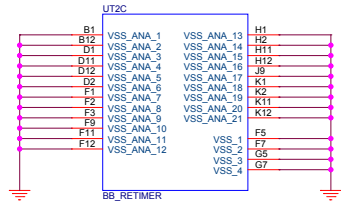
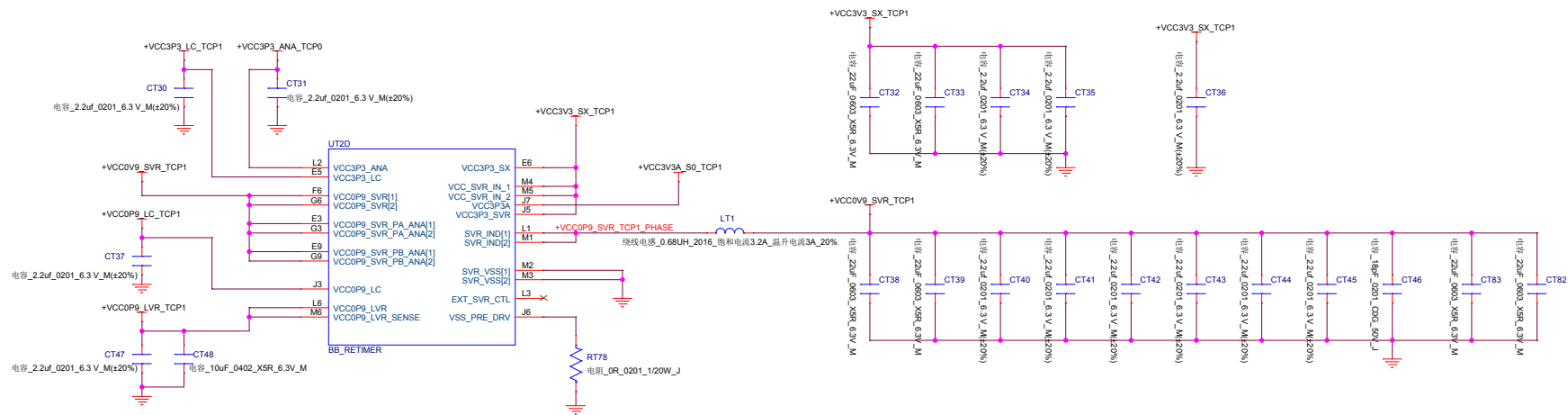
SSD



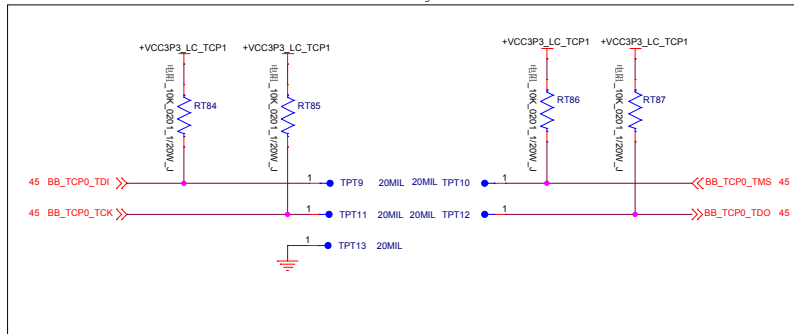




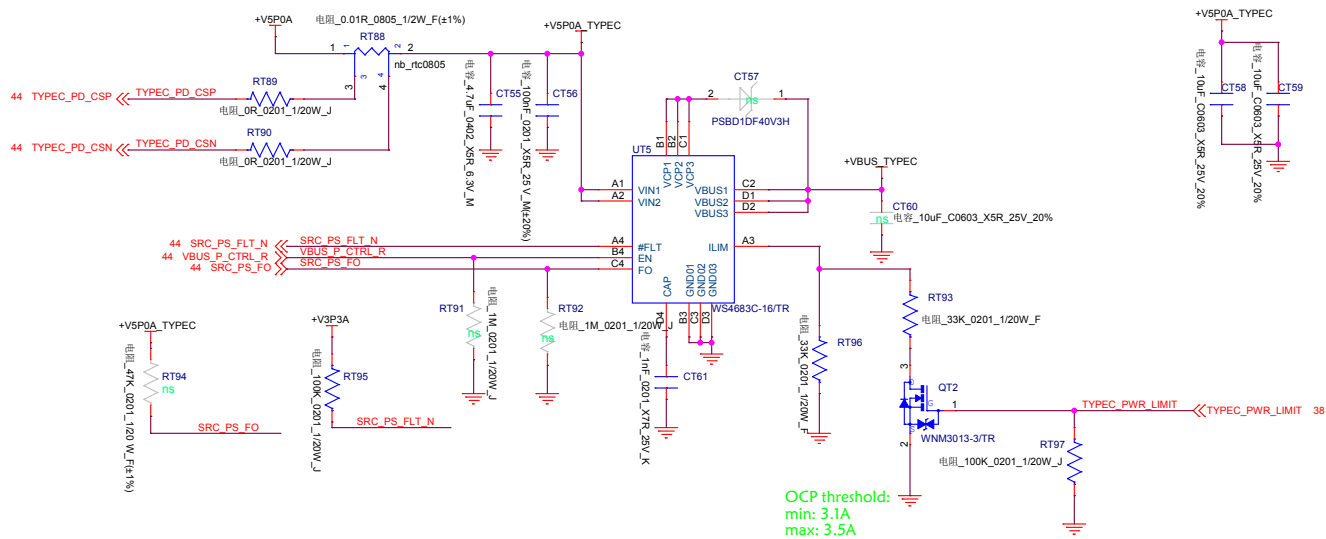




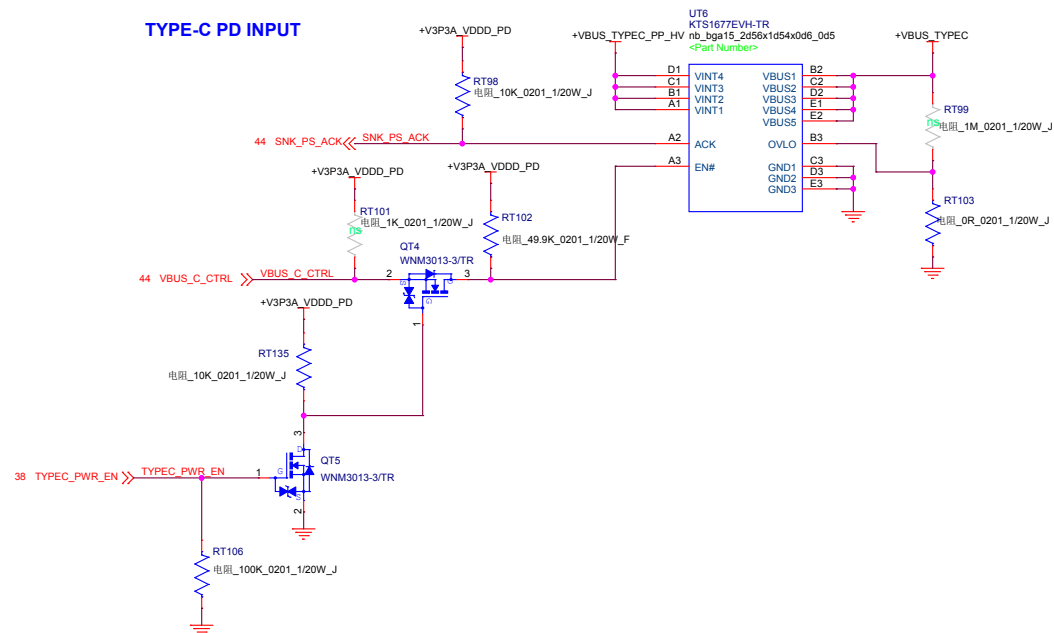
Place together



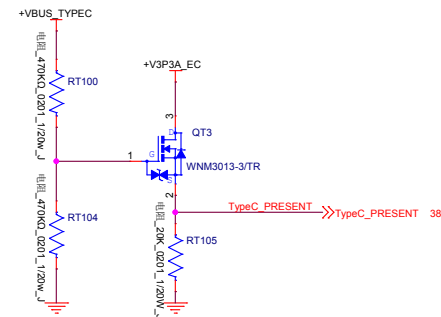
TYPE-C PD OUTPUT



TYPE-C PD INPUT

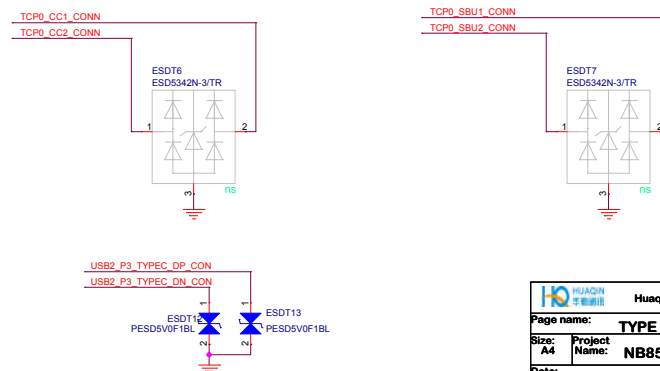
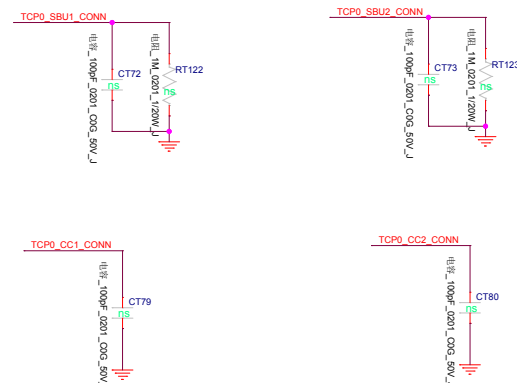
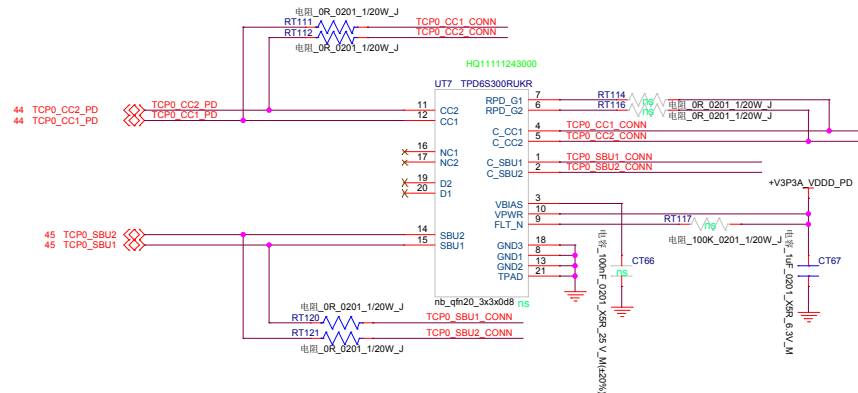
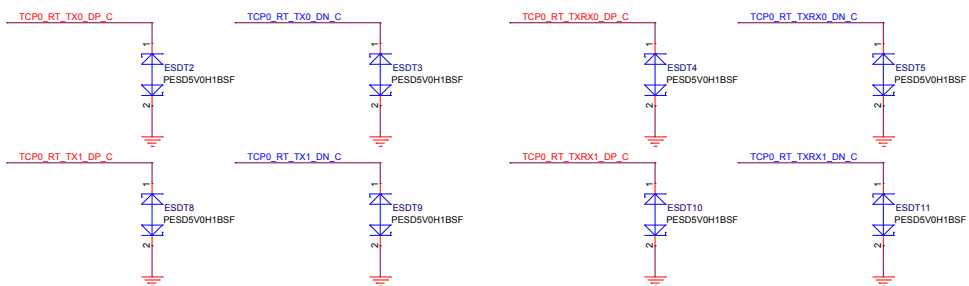
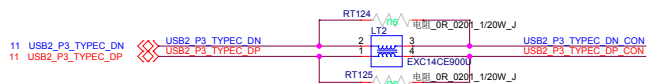
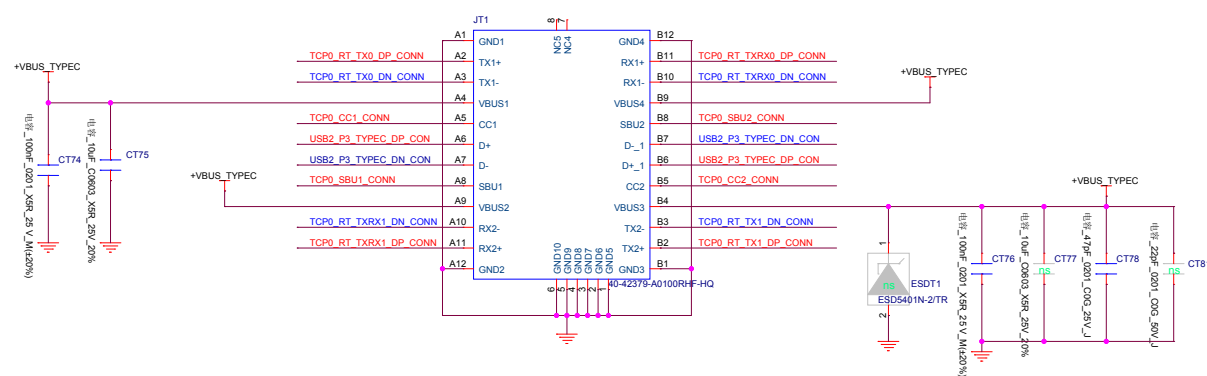
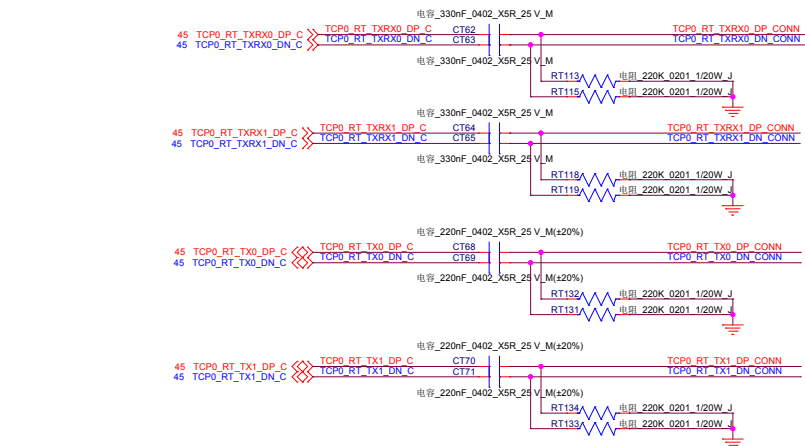


TYPEC-IN detect

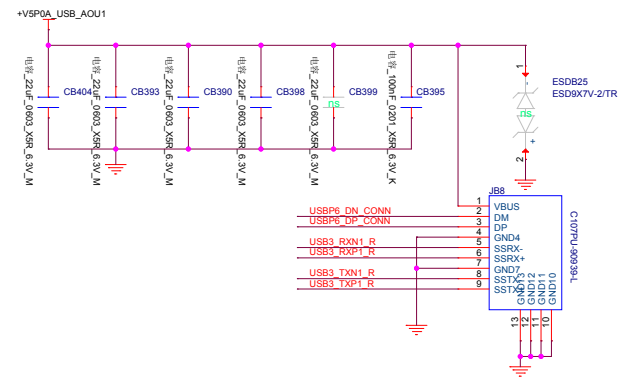
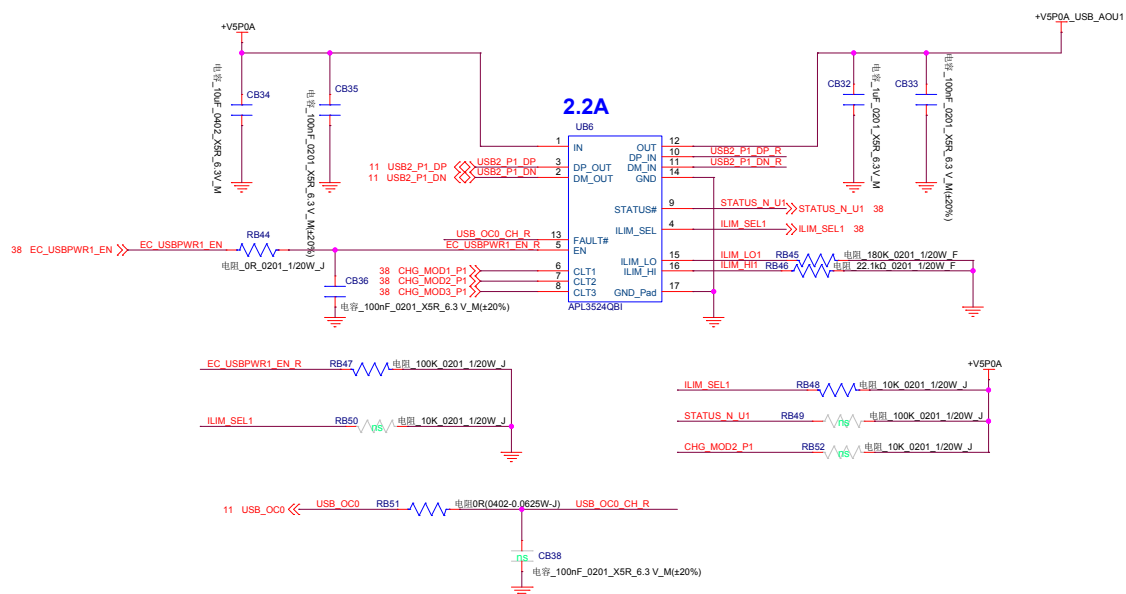


dead battery power on logic

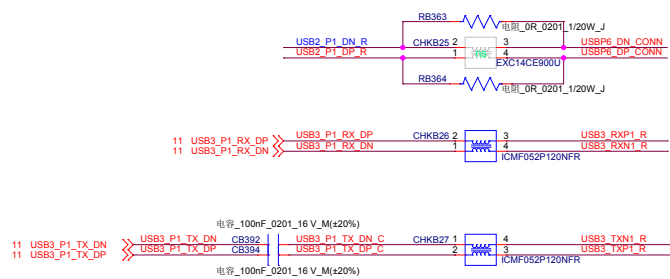
Discharge



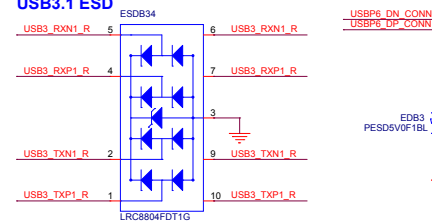
USB3.1 POWER Port1

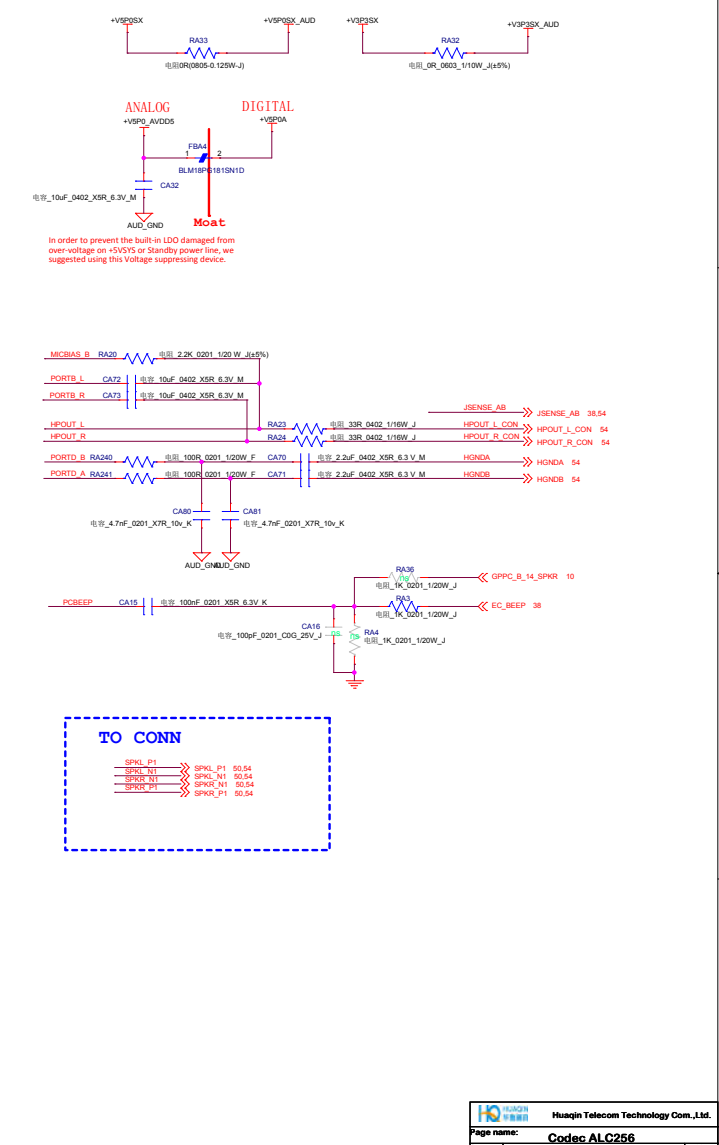
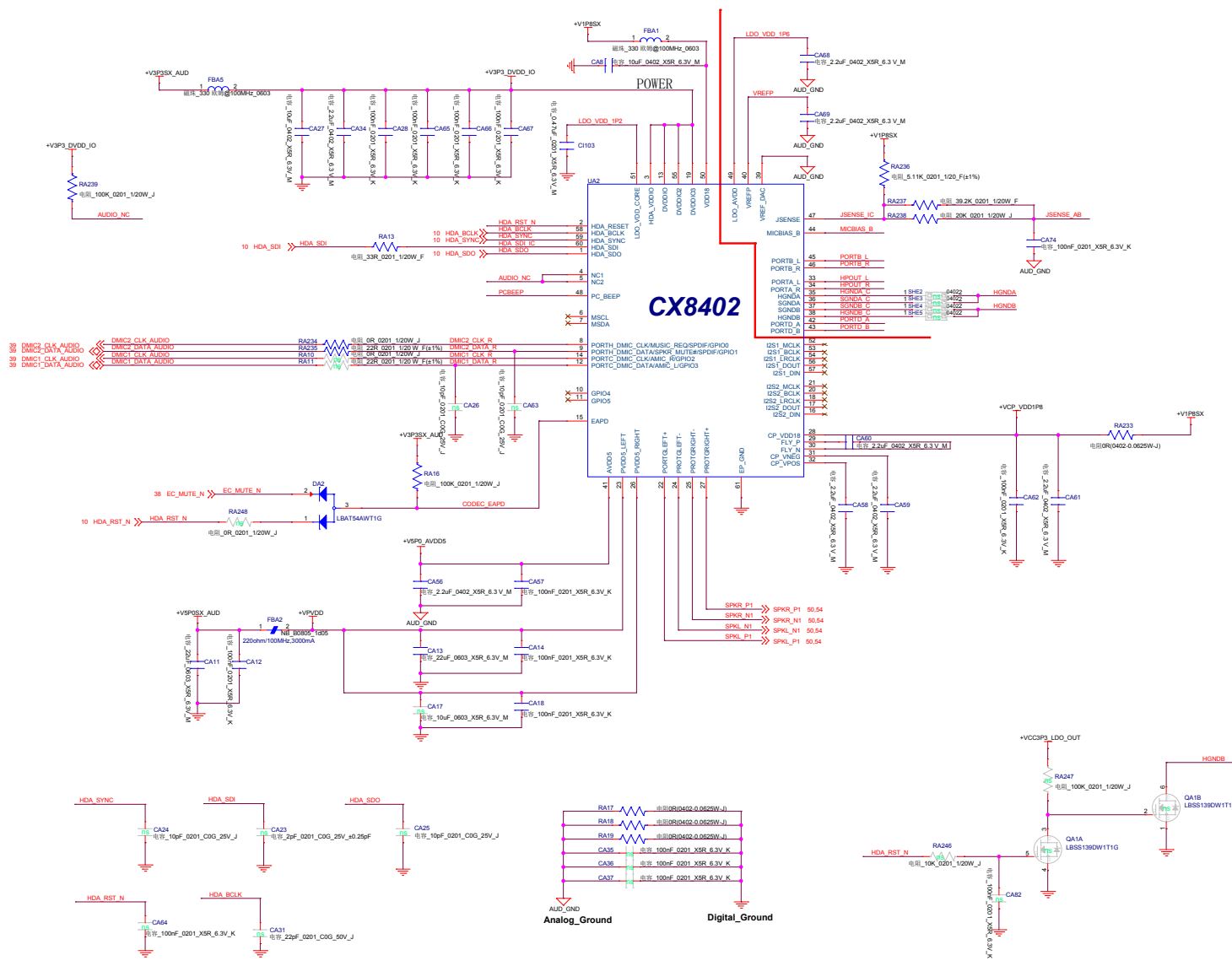


USB3.1 Signal

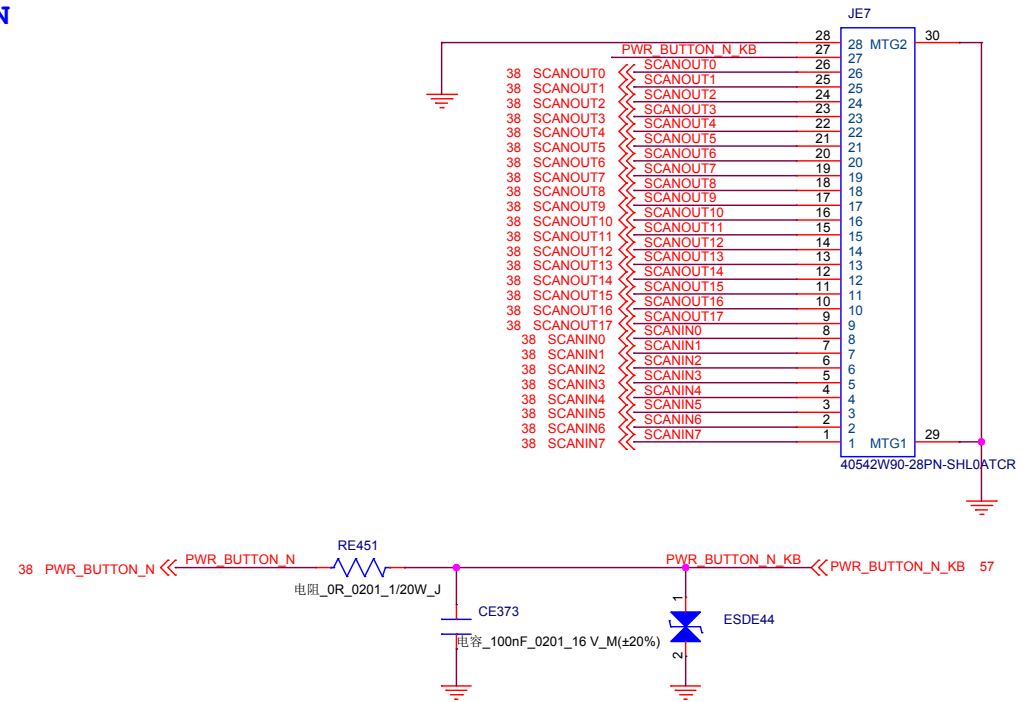
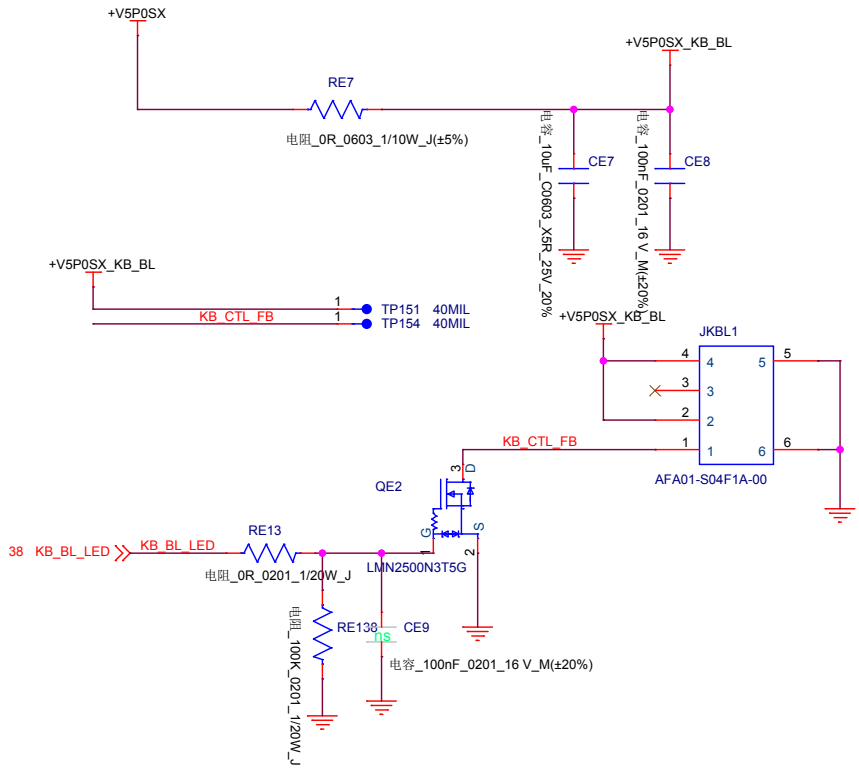


USB3.1 ESD

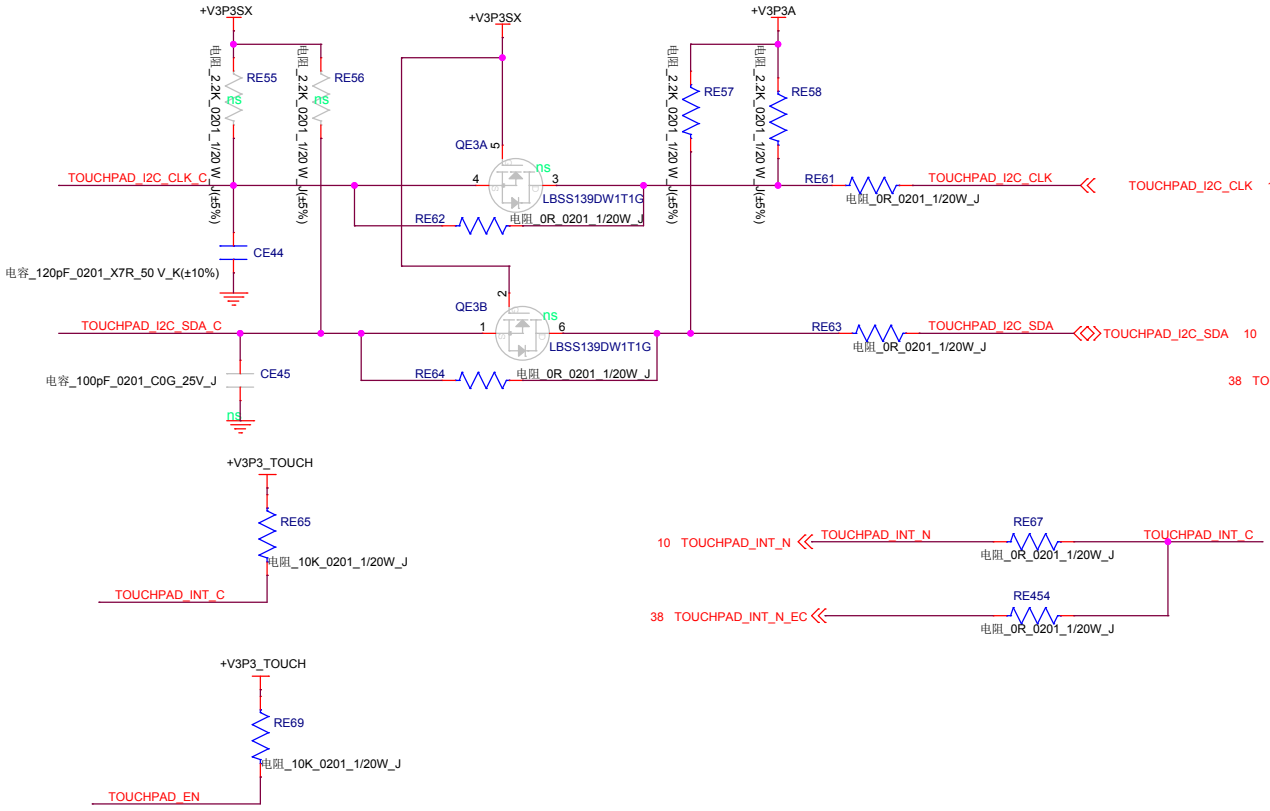




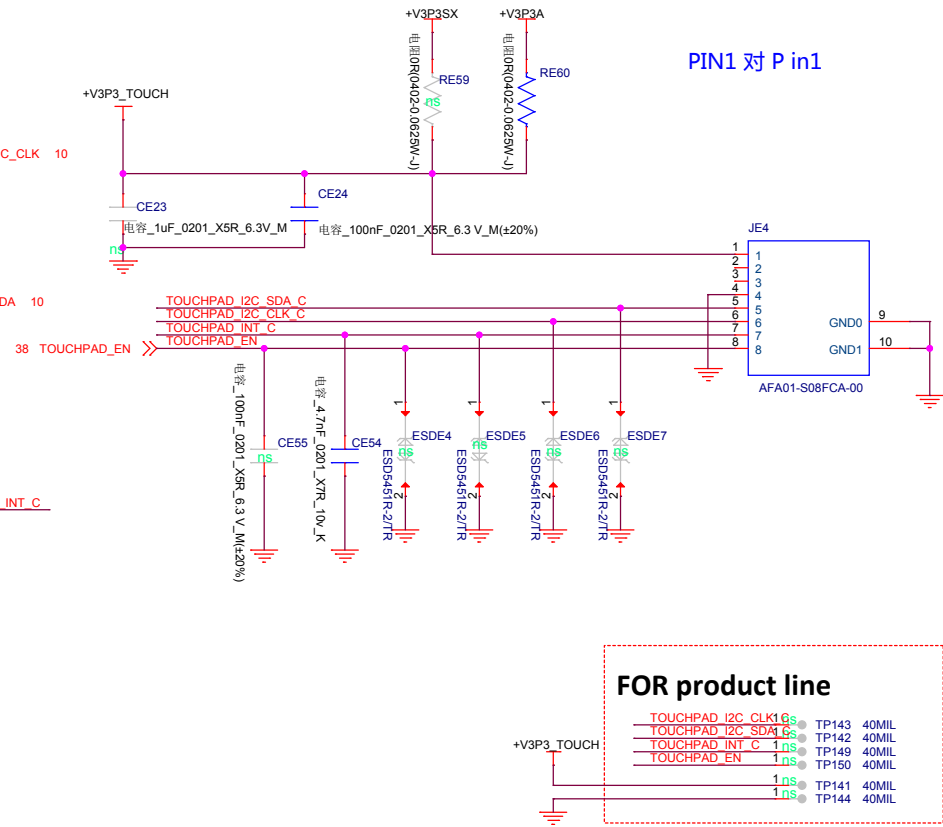
KB CONN



Touch Pad



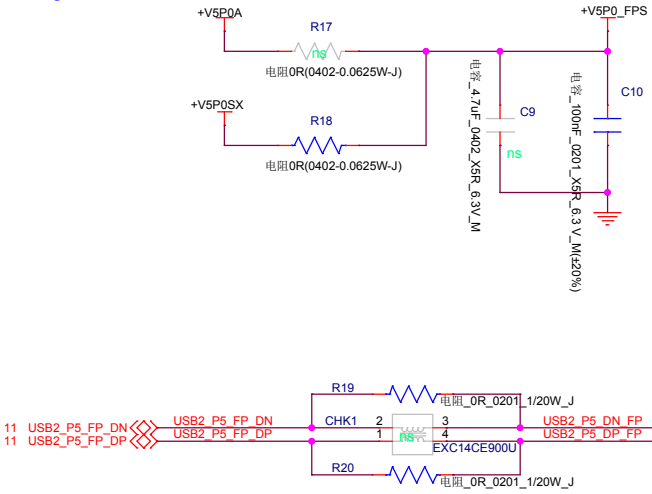
Touch Pad CONN



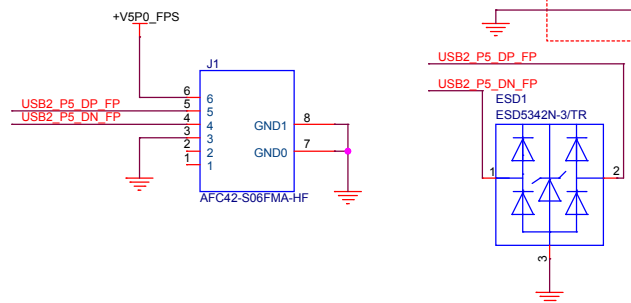
FOR product line

TOUCHPAD_I2C_CLK1	1 nS	TP143	40MIL
TOUCHPAD_I2C_SDA1	1 nS	TP142	40MIL
TOUCHPAD_INT_C	1 nS	TP149	40MIL
TOUCHPAD_EN	1 nS	TP150	40MIL
	1 nS	TP141	40MIL
	1 nS	TP144	40MIL

Finger Print



Finger Print CONN



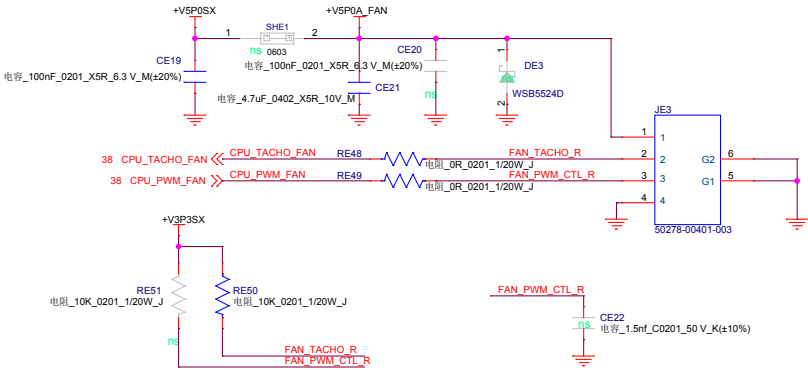
FOR product line

USB2_P5_DP_FP	1 nS	TP147	40MIL
USB2_P5_DN_FP	1 nS	TP146	40MIL
	1 nS	TP145	40MIL
	1 nS	TP148	40MIL

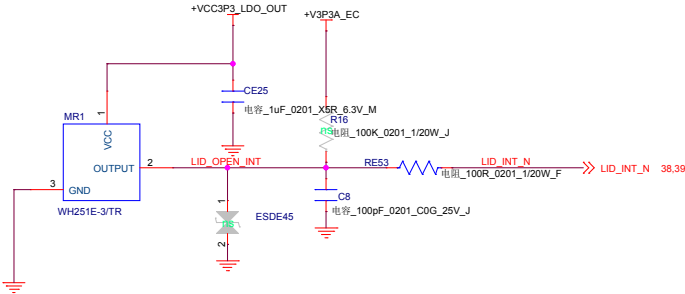
Voice input with LED-NC

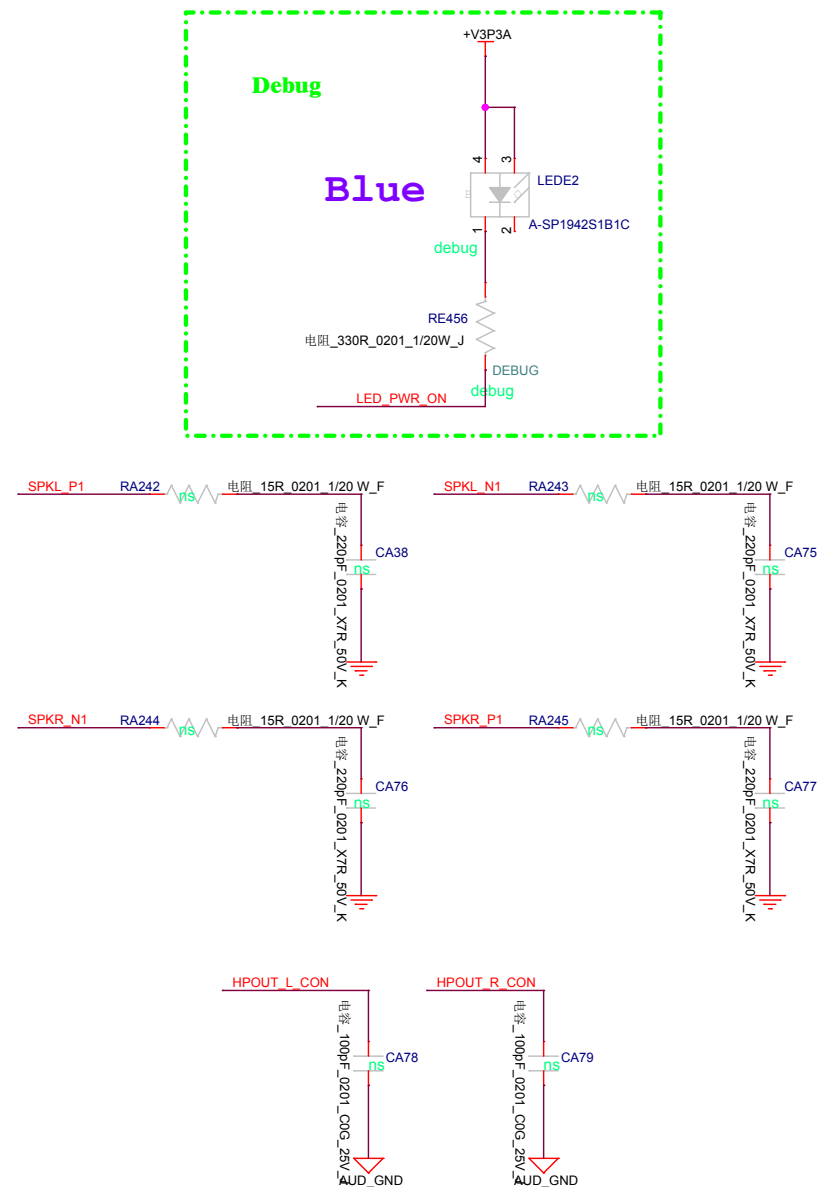
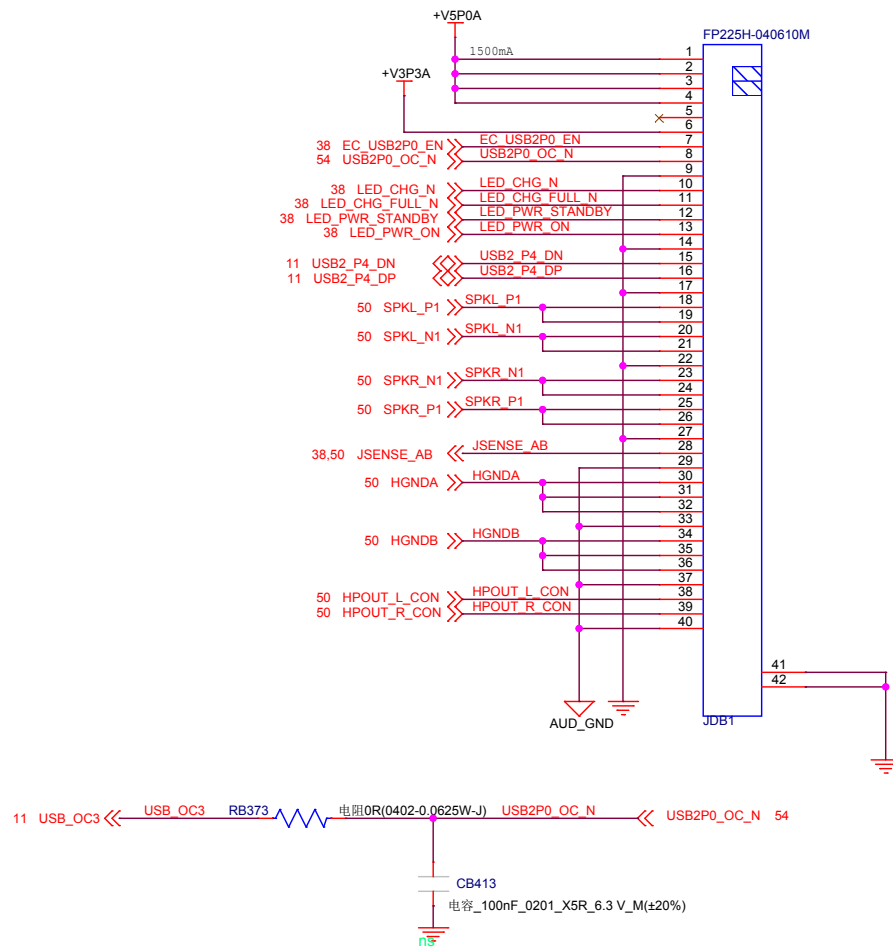
FAN CONN

FOR product line



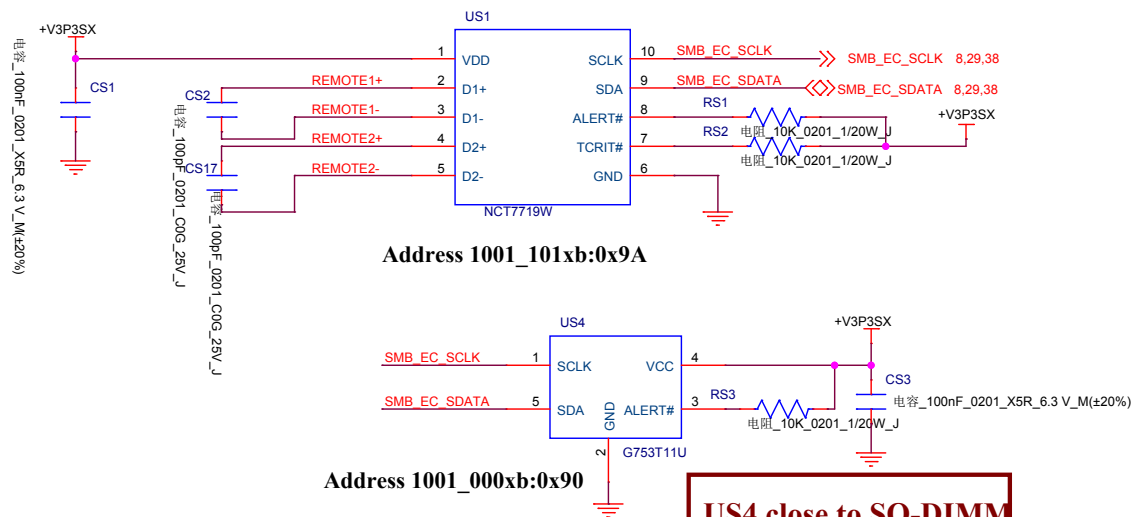
HALL






REMOTE1+/-, Trace width/space:10/10 mil,Trace length:<8"
Connect guard traces to GND on either side of the
DXP-DXN traces

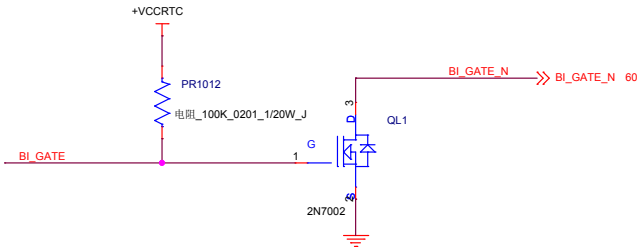
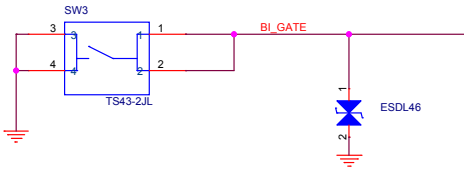
Close to charger



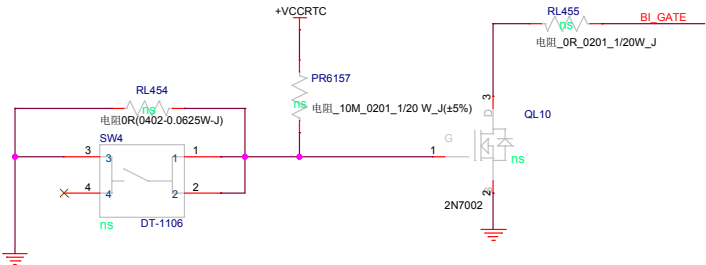
Between CPU and GPU

		Huaqin Telecom Technology Com.,Ltd.	
Page name: Thermal sensor			
Size: A4	Project Name: NB8511		REV: V1.0
Date: Monday, July 15, 2019	Sheet: 56		of 72

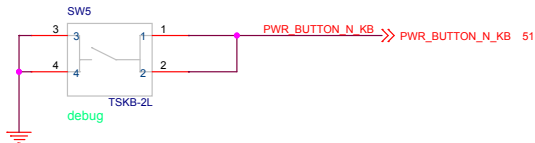
Reset BUTTON



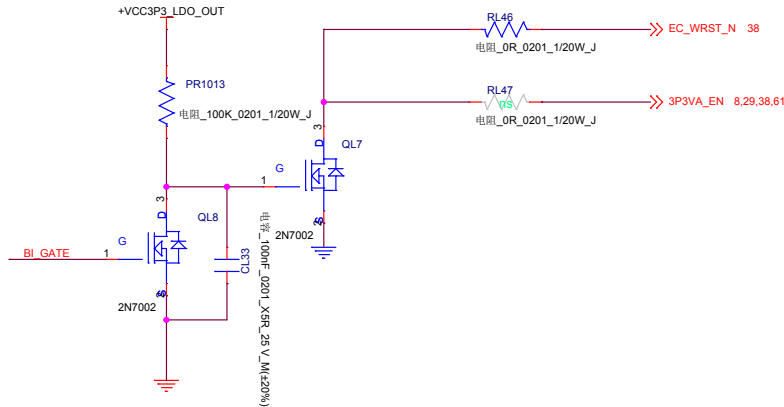
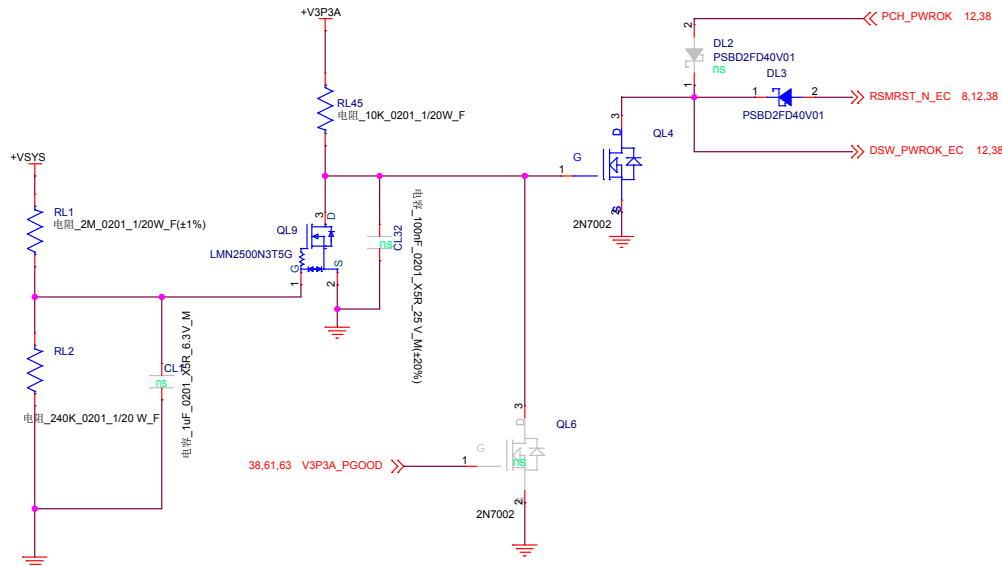
Open door BUTTON



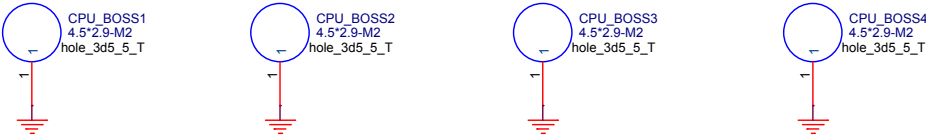
Debug BUTTON



Abnormal PD logic



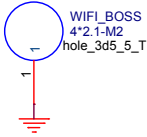
CPU螺母元件 *4



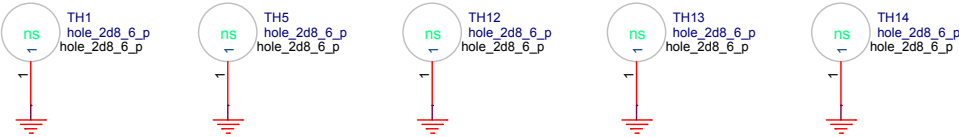
GPU螺母元件 *2



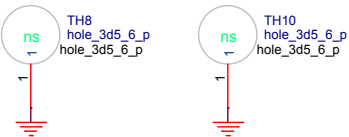
WIFI螺母元件 *1



HOLE *5



HOLE *2



+V1P8A

